

UNITED STATES PATENT AND TRADEMARK OFFICE
DOCUMENT CLASSIFICATION BARCODE SHEET



CATEGORY:

CLEARED

ADDRESS
CONTACT IF FOUND:

FORM PTO-1390 (Modified) (REV 11-98) ²²		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTORNEY'S DOCKET NUMBER
TRANSMITTAL LETTER TO THE UNITED STATES		DESIGNATED/ELECTED OFFICE (DO/EO/US)		NAK1-BN65
CONCERNING A FILING UNDER 35 U.S.C. 371		U.S. APPLICATION NO. (IF KNOWN, SEE 37 CFR		09/744227
INTERNATIONAL APPLICATION NO. PCT/JP00/03154	INTERNATIONAL FILING DATE May 17, 2000	PRIORITY DATE CLAIMED May 20, 1999		
TITLE OF INVENTION METHOD OF PRODUCING GAS DISCHARGE PANEL				
APPLICANT(S) FOR DO/EO/US Hidetaka Hiroshino et al.				
Applicant herewith submits to the United States Designated/Elected Office (DO/EO/US) the following items and other information:				
<ol style="list-style-type: none"> 1. <input checked="" type="checkbox"/> This is a FIRST submission of items concerning a filing under 35 U.S.C. 371. 2. <input type="checkbox"/> This is a SECOND or SUBSEQUENT submission of items concerning a filing under 35 U.S.C. 371. 3. <input type="checkbox"/> This is an express request to begin national examination procedures (35 U.S.C. 371(f)) at any time rather than delay examination until the expiration of the applicable time limit set in 35 U.S.C. 371(b) and PCT Articles 22 and 39(1). 4. <input type="checkbox"/> A proper Demand for International Preliminary Examination was made by the 19th month from the earliest claimed priority date. 5. <input checked="" type="checkbox"/> A copy of the International Application as filed (35 U.S.C. 371 (c) (2)) <ol style="list-style-type: none"> a. <input type="checkbox"/> is transmitted herewith (required only if not transmitted by the International Bureau). b. <input checked="" type="checkbox"/> has been transmitted by the International Bureau. c. <input type="checkbox"/> is not required, as the application was filed in the United States Receiving Office (RO/US). 6. <input checked="" type="checkbox"/> A translation of the International Application into English (35 U.S.C. 371(c)(2)). 7. <input checked="" type="checkbox"/> A copy of the International Search Report (PCT/ISA/210). 8. <input type="checkbox"/> Amendments to the claims of the International Application under PCT Article 19 (35 U.S.C. 371 (c)(3)) <ol style="list-style-type: none"> a. <input type="checkbox"/> are transmitted herewith (required only if not transmitted by the International Bureau). b. <input type="checkbox"/> have been transmitted by the International Bureau. c. <input type="checkbox"/> have not been made; however, the time limit for making such amendments has NOT expired. d. <input checked="" type="checkbox"/> have not been made and will not be made. 9. <input type="checkbox"/> A translation of the amendments to the claims under PCT Article 19 (35 U.S.C. 371(c)(3)). 10. <input checked="" type="checkbox"/> An oath or declaration of the inventor(s) (35 U.S.C. 371 (c)(4)). 11. <input type="checkbox"/> A copy of the International Preliminary Examination Report (PCT/IPEA/409). 12. <input type="checkbox"/> A translation of the annexes to the International Preliminary Examination Report under PCT Article 36 (35 U.S.C. 371 (c)(5)). 				
Items 13 to 20 below concern document(s) or information included:				
<ol style="list-style-type: none"> 13. <input checked="" type="checkbox"/> An Information Disclosure Statement under 37 CFR 1.97 and 1.98. 14. <input checked="" type="checkbox"/> An assignment document for recording. A separate cover sheet in compliance with 37 CFR 3.28 and 3.31 is included. 15. <input checked="" type="checkbox"/> A FIRST preliminary amendment. 16. <input type="checkbox"/> A SECOND or SUBSEQUENT preliminary amendment. 17. <input type="checkbox"/> A substitute specification. 18. <input type="checkbox"/> A change of power of attorney and/or address letter. 19. <input checked="" type="checkbox"/> Certificate of Mailing by Express Mail 20. <input checked="" type="checkbox"/> Other items or information: 				
<p>Copy of PCT Request Copy of International Publication</p>				

U.S. APPLICATION NO. (IF KNOWN), SEE 37 CFR
097744227INTERNATIONAL APPLICATION NO.
PCT/JP00/03154ATTORNEY'S DOCKET NUMBER
NAK1-BN65

21. The following fees are submitted.:

BASIC NATIONAL FEE (37 CFR 1.492 (a) (1) - (5) :

<input type="checkbox"/> Neither international preliminary examination fee (37 CFR 1.482) nor international search fee (37 CFR 1.445(a)(2) paid to USPTO and International Search Report not prepared by the EPO or JPO	\$1,000.00
<input checked="" type="checkbox"/> International preliminary examination fee (37 CFR 1.482) not paid to USPTO but Internation Search Report prepared by the EPO or JPO	\$860.00
<input type="checkbox"/> International preliminary examination fee (37 CFR 1.482) not paid to USPTO but international search fee (37 CFR 1.445(a)(2)) paid to USPTO	\$710.00
<input type="checkbox"/> International preliminary examination fee paid to USPTO (37 CFR 1.482) but all claims did not satisfy provisions of PCT Article 33(1)-(4)	\$690.00
<input type="checkbox"/> International preliminary examination fee paid to USPTO (37 CFR 1.482) and all claims satisfied provisions of PCT Article 33(1)-(4)	\$100.00

CALCULATIONS PTO USE ONLY

ENTER APPROPRIATE BASIC FEE AMOUNT =

\$860.00

Surcharge of \$130.00 for furnishing the oath or declaration later than 20 30 months from the earliest claimed priority date (37 CFR 1.492 (e)).

\$0.00

CLAIMS	NUMBER FILED	NUMBER EXTRA	RATE	
Total claims	49 - 20 =	29	x \$18.00	\$522.00
Independent claims	3 - 3 =	0	x \$80.00	\$0.00
Multiple Dependent Claims (check if applicable).			<input type="checkbox"/>	\$0.00
TOTAL OF ABOVE CALCULATIONS			=	\$1,382.00
Reduction of 1/2 for filing by small entity, if applicable. Verified Small Entity Statement must also be filed (Note 37 CFR 1.9, 1.27, 1.28) (check if applicable).			<input type="checkbox"/>	\$0.00
SUBTOTAL			=	\$1,382.00
Processing fee of \$130.00 for furnishing the English translation later than months from the earliest claimed priority date (37 CFR 1.492 (f)).			<input type="checkbox"/> 20 <input type="checkbox"/> 30 +	\$0.00
TOTAL NATIONAL FEE			=	\$1,382.00
Fee for recording the enclosed assignment (37 CFR 1.21(h)). The assignment must be accompanied by an appropriate cover sheet (37 CFR 3.28, 3.31) (check if applicable).			<input checked="" type="checkbox"/>	\$40.00
TOTAL FEES ENCLOSED			=	\$1,422.00
			Amount to be: refunded	\$
			charged	\$

A check in the amount of \$1,422.00 to cover the above fees is enclosed.

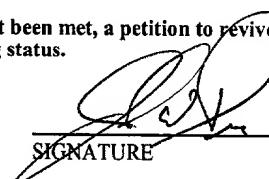
Please charge my Deposit Account No. in the amount of to cover the above fees.
A duplicate copy of this sheet is enclosed.

The Commissioner is hereby authorized to charge any fees which may be required, or credit any overpayment to Deposit Account No. 16-2462 A duplicate copy of this sheet is enclosed.

NOTE: Where an appropriate time limit under 37 CFR 1.494 or 1.495 has not been met, a petition to revive (37 CFR 1.137(a) or (b)) must be filed and granted to restore the application to pending status.

SEND ALL CORRESPONDENCE TO:

Joseph W. Price, Reg. No. 25,124
PRICE AND GESS
2100 S.E. Main St., Ste. 250
Irvine, CA 92614
Tel: 949/261-8433
Fax: 949/261-9071


SIGNATURE

Joseph W. Price

NAME

25,124

REGISTRATION NUMBER

January 22, 2001

DATE

09/744227

NAK1-BN65

22 JAN 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Hidetaka Higashino et al.

Serial No.:

Filed:

For: METHOD OF PRODUCING GAS
DISCHARGE PANEL

Examiner:

Group Art Unit:

Irvine, CA 92614

January 19, 2001

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Prior to an examination on the merits of the above-identified application, please enter the following amendments:

IN THE CLAIMS:

Please amend the claims as follows:

Claim 41, line 2, delete "one of Claims 1 to 40" and insert --Claim 1--;

Claim 44, line 2, delete "one of Claims 1 to 40" and insert --Claim 1--.

Please add the following newly-drafted Claims 48 and 49.

48. The gas discharge panel producing method according to Claim 2, wherein the cleaning gas is the discharge gas.

49. The gas discharge panel producing method according to Claim 2, wherein the light emitting cells are formed by positioning a first group of parallel electrodes on the first plate orthogonally to a second group of parallel electrodes on the second plate with a distance between the first and second electrode groups.

REMARKS

The amendments to the claims are to remove multiple dependency and to correct minor grammatical errors.

Newly drafted Claims 48 and 49 are within the scope of the original invention and do not add any new subject matter.

If the Examiner believes that a telephone interview will help further the prosecution of this case, he is respectfully requested to contact the undersigned attorney at the listed telephone number.

Very truly yours,

PRICE AND GESS



Joseph W. Price, Reg. 251,24
2100 S.E. Main St., Ste. 250
Irvine, CA 92614
949/261-8433

DESCRIPTIONMethod of Producing Gas Discharge Panel5 FIELD OF THE INVENTION

The present invention relates to the method of producing the gas discharge panel such as the plasma display panel used for displaying images on computer and TV monitors.

10

BACKGROUND OF THE INVENTION

An explanation of the conventional plasma display panel will be given with reference to figures. Fig. 8 is a simplified sectional view of the AC plasma display panel (hereinafter, referred to "PDP").

In Fig. 8, a reference number 110 indicates a front glass plate. On the front glass plate 110, display electrodes 111 are formed. The display electrodes 111 are covered by a dielectric glass layer 112 and a dielectric protection layer 113 made of magnesium oxide (MgO) (refer to Japanese Patent Laid-Open Publication No. 5-342991).

Meanwhile, a reference number 120 indicates a back glass plate. On the back glass plate 120, address electrodes 121, a visible light reflective layer 122 for covering the address electrodes 121, partition walls 123,

and phosphor layers 124 are disposed. A reference number 130 indicates a discharge space filled with a discharge gas. For color display, each of the phosphor layers 124 is red, green or blue and the phosphor layers 124 are disposed in this order. Each of the phosphor layers 124 is excited by short ultraviolet light of a short wavelength (for instance, 147nm) that has been generated by discharge and emits light.

Generally, the phosphors described below are used for the phosphor layers 124.

"Blue phosphor": $\text{BaMgAl}_{10}\text{O}_{17}:\text{Eu}$

"Green phosphor": $\text{Zn}_2\text{SiO}_4:\text{Mn}$ or $\text{BaAl}_{12}\text{O}_{19}:\text{Mn}$

"Red phosphor": $\text{Y}_2\text{O}_3:\text{Eu}$ or $(\text{Y}_x\text{Gd}_{1-x})\text{BO}_3:\text{Eu}$

Now, the method of producing each of the phosphors will be described.

The blue phosphor ($\text{BaMgAl}_{10}\text{O}_{17}:\text{Eu}$) is manufactured as follows. First, barium carbonate (BaCO_3), magnesium carbonate (MgCO_3), and aluminium oxide ($\alpha\text{-Al}_2\text{O}_3$) are blended so that the atomic ratio of barium (Ba), magnesium (Mg), and aluminium (Al) is 1:1:10.

Next, a predetermined amount of europium oxide (Eu_2O_3) is added to the mixture. Then, the mixture is blended with an appropriate amount of flux (AlF_3 , BaCl_2) in a ball mill. The mixture that has been blended with the flux is calcinated at 1400 to 1650°C for a predetermined amount of time (for instance, 0.5 hours) in

a reducing atmosphere (in H_2 or N_2) to obtain the blue phosphor.

The red phosphor ($Y_2O_3:Eu$) is manufactured as follows. The raw materials for the red phosphor, yttrium hydroxide ($Y_2(OH)_3$) and boric acid (H_3BO_3) are blended so that the atomic ratio between yttrium and boric is 1:1. Then, a predetermined amount of europium oxide (Eu_2O_3) is added to the mixture. The mixture is blended with an appropriate amount of flux in a ball mill and is calcinated at 1200 to 1450°C for a predetermined amount of time (for instance, 1.0 hour) in the air to obtain the red phosphor.

The green phosphor ($Zn_2SiO_4:Mn$) is manufactured as follows. The raw materials for the green phosphor, zinc oxide (ZnO) and silicon oxide (SiO_2) are blended so that the atomic ratio between zinc and silicon is 2:1. Then, a predetermined amount of manganese oxide (Mn_2O_3) is added to the mixture and blended in a ball mill. The mixture is calcinated at 1200 to 1350°C for a predetermined amount of time (for instance, 0.5 hours) in the air to obtain the red phosphor.

Particles of each of the phosphors that has been obtained in the above-described method are grounded to powders and then sieved to obtain phosphor materials having a predetermined particle distribution.

Here, an explanation of the conventional

producing method of PDP will be given below.

First, display electrodes are formed on the front glass plate. The dielectric layer made of a dielectric glass is formed so as to cover the display electrodes.

5 On the dielectric layer, the protection layer is formed made of MgO. Then, the address electrodes are formed on the back glass plate. On the address electrodes, the visible light reflective layer made of a dielectric glass is formed. On the address electrodes, glass partition 10 walls are formed with a predetermined pitch.

In the spaces between the partition walls, phosphor pastes which each include the red, green, and blue phosphors are put, respectively to form the phosphor layer. The phosphor layer is calcinated at approximately 15 500°C to remove the resin component and the like in the pastes (the phosphor calcination process).

After the phosphor calcination, a glass frit for sealing the apertures between the front and back glass plates is applied onto the outer edge of the back glass 20 plate, and the back glass plate is calcinated at 350°C (the glass calcination process for sealing).

Then, the front glass plate on which the display electrodes, the dielectric glass layer, and the protection layer have been formed in order and the back 25 glass plate are positioned so as to face each other. In this case, the front and back glass plates are positioned

so that the display electrodes and the address electrodes intersect orthogonally via the partition walls. Then, the front and back glass plates are calcinated at 450°C to seal the front and back glass plates along the outer 5 edges with sealing glass (the sealing process).

After the sealing process, while the panel is heated to a predetermined temperature (approximately 350°C), the air is exhausted from the panel (the exhaust process). After the exhaust process, the panel is filled 10 with the discharge gas at a predetermined pressure.

In the above-described producing method of PDP, the light emitting properties gradually deteriorate after panel production, in the aging process for stabilizing the discharge properties, and in the normal operation. 15 This is problematic.

This is because impurities (gas components different from the discharge gas such as water vapor, oxygen, nitrogen, and carbon dioxide) in the internal spaces are not completely cleaned and remain in the 20 internal spaces in the exhaust process.

DISCLOSURE OF THE INVENTION

It is accordingly the object of the present invention to provide a method of producing a gas discharge panel that efficiently exhausts gas in the 25 vacuum pumping process, which is necessary to the panel

producing processes.

The above-mentioned object may be achieved by a method of producing a gas discharge panel that includes: an envelope forming step for forming an envelope by providing over a first plate a second plate so that the second plate faces a main surface of the first plate, on which partition walls for partitioning light emitting cells have been formed; a sealing step for sealing the envelope with a sealant along outer edges of the first and second plates; an exhaust step for exhausting gas from the envelope; and a filling step for filling the envelope with a discharge gas, wherein the exhaust step includes: a substep for evacuating the envelope; a substep for filling the envelope with a cleaning gas that includes as a constituent a gas that substantially causes no impurity in the discharge gas; and a substep for re-evacuating the envelope.

10
15
20
25

The above-mentioned object may be also achieved by a method of producing a gas discharge panel that includes: an envelope forming step for forming an envelope by providing over a first plate a second plate so that the second plate faces a main surface of the first plate, on which partition walls for partitioning light emitting cells have been formed; a sealing step for sealing the envelope with a sealant along outer edges of the first and second plates; an exhaust step for

exhausting gas from the envelope; and a filling step for
filling the envelope with a discharge gas, wherein the
exhaust step includes: a substep for evacuating the
envelope; and a substep for exhausting gas from the
envelope while a cleaning gas is circulated through the
envelope, the cleaning gas including as a constituent a
gas that substantially causes no impurity in the
discharge gas.

Note that the "includes as a constituent a gas
that substantially causes no impurity in the discharge
gas" means that "the major constituent of the cleaning
gas causes no impurities in the discharge gas".

Unlike the conventional method, gas is not only
exhausted from the envelope as in the case of the
conventional producing method. According to these
producing methods, gas is exhausted from the envelope
after the envelope is filled with the cleaning gas or
while the cleaning gas is circulated through the
envelope. As a result, the concentration of impurity gas
in the envelope can be swiftly (in a short period of
time) lowered compared with the conventional method.

Also, when the pressure in the envelope is set to
be lower than the pressure outside of the envelope while
the entire envelope or the sealed part is heated to a
temperature that is no lower than the softening point or
the melting point of the sealant at the sealing step in

the producing methods, the sealant hardens to seal the envelope while the first and second plates are evenly pressed from the outside due to the pressure difference between the inside and the outside of the envelope. As a 5 result, the envelope is sealed so that the entire top ends of the partition walls almost come in contact with the plate that faces the partition walls. According to the conventional method, the pressures inside and outside of the envelope are not set to be different and only the 10 outer edges are tightly held with clips, so that the central parts of the first and second plates of the envelope are not pressed. As a result, the entire or part of the top ends of the partition walls tends to be apart from the facing plate when the envelope is sealed.

15 Accordingly, it is easy to produce a PDP with rare vibration at the time of drive and with excellent display quality according to the methods described above.

Also, when the envelope is filled with the dry 20 gas at the sealing step, heat deterioration of the phosphors can be prevented.

BRIEF DESCRIPTION OF THE DRAWINGS

These and other objects, advantages and features 25 of the invention will become apparent from the following description thereof taken in conjunction with the accompanying drawings that illustrate a specific

embodiment of the invention. In the Drawings:

Fig. 1 is a perspective view showing the structure of an AC plasma display panel (PDP) according to the embodiments of the present invention;

5 Fig. 2 shows the structure of a display device that is the PDP equipped with a circuit block;

Fig. 3 is diagrammatic sketches of a sealing/exhausting device 50 used in a sealing process of the first embodiment;

10 Fig. 3(a) is an overhead cutaway view of the seal/exhaust device 50;

Fig. 3(b) is a vertical sectional view taken on line A-A' of Fig. 3(a);

15 Fig. 4 shows temperature and pressure profiles during sealing (practical example);

Fig. 5 shows temperature and pressure profiles in an vacuum pumping/filling process (practical example);

20 Fig. 6 shows temperature and pressure profiles during sealing and in the vacuum pumping/filling process (practical example);

Fig. 7 is a diagrammatic sketch of a sealing/exhausting device 70 used in a sealing process of the second embodiment; and

25 Fig. 8 is a perspective view showing the structure of a PDP according to a conventional example.

DESCRIPTION OF THE PREFERRED EMBODIMENTS

A specific explanation of a producing method of a PDP according to the present invention will be given below with reference to figures.

5

[Overall Structure and Producing Method of PDP]

Fig. 1 is a perspective view showing the structure of an AC surface discharge type PDP according to the embodiments of the present invention. Fig. 2 10 shows the structure of a display device that is the PDP equipped with a circuit block.

15 In the PDP, pulsed voltage is applied between the electrodes for discharge in the discharge spaces. Along with the discharge, visible lights of different colors are generated on the side of the back panel. The visible lights is emitted through the front panel.

20 The PDP is composed of a front panel 10 and a back panel 20. The front panel 10 is formed by disposing a plurality of display electrodes 12 (scan electrodes 12a and sustain electrodes 12b), a dielectric layer 13, and a protection layer 14 on a front glass plate 11. On the other hand, the back panel 20 is formed by disposing a plurality of address electrodes 22 and dielectric layer 23 on a back glass plate 21. The front and back panels 25 are positioned so that the scan and sustain electrodes 12a and 12b and the address electrodes 22 face to each

other at a distance.

The center of the PDP is an area for displaying an image. The space between the front and back panels 10 and 20 are separated by a plurality of partition walls 24 that run in parallel to form a plurality of discharge spaces 30. The discharge spaces 30 are filled with discharge gas. In each of the discharge spaces 30, a phosphor layer 25 is disposed on the back panel 20. Different color phosphor layers 25, i.e., red, green, and blue phosphor layers 25 are repeatedly arranged in this order.

The display electrodes 12 and the address electrodes 22 are disposed in parallel, respectively. The display electrodes 12 are disposed orthogonally to and the address electrodes 22 in parallel to the partition walls 24.

As a result, cells which each emit red, green, and blue lights are formed where the display electrodes 12 and the address electrodes 22 intersect in the panel.

The dielectric layer 13 covers the entire surface of the front glass plate 11 on which the display electrodes 12 are disposed. The dielectric layer 13 is made of a dielectric substance. Low melting point lead glass is generally used. Low melting point bismuth glass, or layers of low melting point lead glass and low melting point bismuth glass may be also used.

The protection layer 14 is a thin film made of magnesium oxide (MgO). The protection layer 14 covers the entire surface of the dielectric layer 13. Having the function of the visible light reflective layer, TiO_2 particles are blended in the dielectric layer 23. The partition walls 24 are made of a glass material and are disposed on the surface of the dielectric layer 23 of the back panel 20 in a protruding condition.

Meanwhile, the front and back panels 10 and 20 are sealed with a sealant along the outer edge of the PDP.

The entire top ends of the partition walls 24 approximately come in contact with or are joined to the front panel 10 with a bonding material.

Here, an example of a producing method of the above-described PDP will be described.

(Manufacturing Front Panel)

The display electrodes 12 are formed on the front glass electrode 11. The dielectric layer 13 is formed so as to cover the display electrodes 12 and the front glass electrode 11. Then, on the surface of the dielectric layer 13, the protection layer 14 made of MgO is formed in the vacuum evaporation method, the electron beam evaporation method, or the CVD (Chemically Vapor Deposition) method. In this manner, the front panel is

manufactured.

The display electrodes 12 are formed by applying a silver electrode paste on the front glass electrode in the screen printing method and calcinating the paste.

5 Also, silver electrodes may be formed after forming transparent electrodes with ITO (Indium Tin Oxide) or SnO_2 (tin dioxide), or Cr-Cu-Cr electrodes may be formed in the photo photolithographic method.

10 The dielectric layer 13 can be formed by applying a paste including a lead glass material (the composition is 70wt% of lead oxide (PbO), 15wt% of (B_2O_3), and 15wt% of silicon oxide (SiO_2), for instance) on the front glass plate 11 in the screen printing method and calcinating the paste.

15 (Manufacturing Back Panel)

On the back glass plate 21, the address electrodes 22 are formed in the screen printing method as in the case of the display electrodes 12.

20 Then, the dielectric layer 23 is formed by applying a glass material with which TiO_2 particles have been blended on the back glass plate 21 in the screen printing method and calcinating the paste.

25 Next, the partition walls 24 are formed. The partition walls 24 are formed by applying a partition wall glass paste on the back glass plate 21 in the screen

printing method and calcinating the paste. The partition walls 24 can be also formed by applying a partition wall glass paste on the entire surface of the back glass plate 21 and removing the paste from the parts where the 5 partition walls 24 are not formed in the sand blast method.

In the channels between the partition walls, the phosphor layers 25 are formed. Generally, the phosphor layers 25 are formed by applying the phosphor pastes each 10 of which includes phosphor particles of a different color in the screen printing method and calcinating the applied phosphor pastes. The phosphor layers 25 may be formed by continuously spraying phosphor inks from a nozzle on the channels while the nozzle scans the channels and 15 calcinating the phosphor inks in order to remove the solvents and binders included in the phosphor inks. In each of the phosphor inks, phosphor particles of a different color are dispersed in a mixture of a binder, a solvent, a dispersant, and the like. The phosphor inks 20 are adjusted so as to have an appropriate viscosity.

The following is specific examples of the phosphor particles.

Blue phosphor: $\text{BaMgAl}_{10}\text{O}_{17}:\text{Eu}^{2+}$

Green phosphor: $\text{BaAl}_{12}\text{O}_{19}:\text{Mn}$ or $\text{Zn}_2\text{SiO}_4:\text{Mn}$

25 Red phosphor: $(\text{Y}_x\text{Gd}_{1-x})\text{BO}_3:\text{Eu}^{3+}$ or $\text{YBO}_3:\text{Eu}^{3+}$

In the preferred embodiments of the present

invention, the height of the partition walls is set to be 0.06 to 0.15mm and the pitch between the partition walls is 0.13 to 0.36mm in line with the Video Graphics Array (VGA) and high-definition TV set of 40 inch class.

5

(Sealing Process, Vacuum Pumping Process, and Discharge Gas Filling Process)

Next, the front panel 10 and the back panel 20 are sealed.

10 In the sealing process, the front panel 10 is provided on the back panel 20 and a sealant is inserted between the front panel 10 and the back panel 20 along the outer edges to form an envelope. The apertures between the front panel 10 and the back panel 20 along the outer edges are sealed with the sealant. When 15 necessary, a bonding material can be applied on the top of the partition walls of the back panel 20.

20 The sealant is a material that is softened by energy such as heat from outside. Generally, low-melting glass is used as the bonding material. In the sealing process, the sealant is softened by heat and then hardened.

25 Also, in the sealing process, the pressures inside and outside of the envelope are set to be different so as to evenly apply pressure to the front panel 10 and the back panel 20 from the outside. By

doing so, the entire top ends of the partition walls 24 come in contact with or come closer to the front panel 10 in the sealing.

After the sealing process, a high vacuum (1.3×10^{-11} MPa, for instance) is produced in the internal space to exhaust air in order to expel impurity gas that has been absorbed in the inside of the envelope (vacuum pumping process).

Then, the envelope is filled with a discharge gas (He-Xe, Ne-Xe, and Ar-Xe inert gas, for instance) at a predetermined pressure (discharge gas filling process). By doing so, the PDP is produced.

Note that Xe constitutes approximately 5vol% of the discharge gas and the pressure for filling is set in the range of 0.067 to 0.11Mpa in the preferred embodiments of the present invention

When driven for display, the PDP is equipped with a circuit block as shown in Fig. 2.

Explanations of the sealing process, the vacuum pumping process, and the discharge gas filling process will be given below in the first to fourth embodiments.

(The First Embodiment)

Fig. 3 is diagrammatic sketches of a sealing/exhausting device 50 used in the sealing process

of the first embodiment. Fig. 3(a) is an overhead cutaway view of the sealing/exhausting device 50 and Fig. 3(b) is a vertical sectional view taken on line A-A' of Fig. 3(a).

5 In the sealing/exhausting device 50, the envelope 40, which is formed by providing the front panel 10 on the back panel 20, is enclosed. The sealing/exhausting device 50 also includes a heating furnace 51 for applying heat to the envelope 40, a gas introducing system 52 that 10 is equipped outside of the heating furnace 51, and a suction exhaust system 53.

To the heating furnace 51, heat can be applied by a heater 54. The internal temperature can be set at a desired temperature.

15 The sealing process is performed using the sealing/exhausting device 50 as follows.

As shown in Fig. 3, ventilation slots 21a and 21b are opened in advance in the back panel 20 at the regions that are positioned outside of the display area. The 20 ventilation slot 21a is opened at the upper right of the back panel 20, while the ventilation slot 21b is at the bottom left in Fig. 3(a).

A paste including a sealant is applied to at least one of the joining surfaces of the front panel 10 and the back panel 20 along the outer edges. Then, the 25 paste is calcinated to form a sealant layer 41. Here, a

low-melting glass having a softening temperature lower than the materials of the dielectric layer 23 and the partition wall 24 is used as the sealant. Note that the sealant is not limited to the low-melting glass. Metals 5 can be used. In this case, the temperature for sealing is the temperature at which the metal melts.

Accordingly, the sealing temperature is higher than the melting point.

A specific example of the low-melting glass is 10 the mixture of 80wt% of a low-melting glass frit (the softening temperature is 370°C), 5wt% of an ethyl cellulose binder, and 15wt% of isoamyl acetate. By applying the mixture with a dispenser, the sealant layer 41 is formed.

15 Between the sealant layer 41 and the outermost partition walls, partition members 42 are disposed so as to halve the spaces between the sealant layer 41 and the partition walls 24. The material of the partition members 42 can be the same as the material of the sealant layer 41 and the partition walls 24. Due to the partition members, gas is effectively introduced into and exhausted from the discharge spaces between the partition walls 24. Note that the partition members 42 cannot be disposed.

20 Then, the front panel 10 is provided on the back panel 20 to form the hosing 40 while it is checked that

the front and back panels 10 and 20 are properly positioned. The outer edge of the envelope 40 is tightly held with clips (not illustrated) so that the front and back panels 10 and 20 do not shift the positions.

5 The envelope 40 is set inside of the heating furnace 51. Then, the gas introducing system 52 is connected to the ventilation slot 21a of the envelope 40 via a connecting tube 55. On the other hand, the suction exhaust system 53 is connected to the ventilation slot 21b of the envelope 40 via a connecting tube 56.

10 The connecting tubes 55 and 56 are glass tubes that are fixed to the back panel 20 at the lower surface via bonding members 55a and 56a. The material of the bonding members 55a and 56a is the same as the material of the sealant layer 41. More specifically, a paste including the low-melting glass is applied to the back panel 20 with a dispenser. Then, the paste is dried and the connecting tubes 55 and 56 are tentatively fastened to the back panel 20 with clips. By doing so, as the sealant layer 41 is softened and hardened to seal the envelope, the bonding members 55a and 56a are also softened and hardened. As a result, the connecting tubes 55 and 56 are connected to the ventilation slots 21a and 21b and the apertures between the connecting tubes 55 and 25 56 and the ventilation slots 21a and 21b are sealed.

The gas introducing system 52 includes a gas bomb

52a and a pipe system 52b, which connects the gas bomb 52a to the connecting tube 55. In the midst of the pipe system 52b, an open/close valve 52c is disposed for adjusting the amount of gas to be introduced. The 5 connecting tube 55 and the pipe system 52b are connected to each other with a chuck so as to ensure airtightness.

The suction exhaust system 53 includes a manifold 53a, a turbo-molecule pump 53b, a rotary pump 53c, and pipe systems 53d and 53e. The pipe system 53d connects the connecting tube 56 to the manifold 53a. On the other hand, the pipe system 53e connects the manifold 53a to the turbo-molecule pump 53b. In the midst of the pipe system 53e, an open/close valve 53f is disposed for adjusting the amount of gas sucked out by the turbo-molecule pump 53b. The connecting tube 56 and the pipe system 53d are connected to each other with a chuck so as to ensure airtightness.

Note that the front panel 10 is provided on the back panel 20 in the present embodiment. However, the 20 back panel 20 may be provided on the front panel 10 instead. Also, as long as the front and back panels 10 and 20 are held together so as not to shift the positions, the envelope 40 can be vertically set in the heating furnace.

25 The heating furnace 51 is heated to the sealing temperature that is slightly higher than the softening

temperature of the sealant (for instance, 450°C). Then, the heating furnace 51 is kept at the sealing temperature for a certain period of time and the temperature is lowered to a temperature that is no higher than the 5 softening temperature. By doing so, the apertures between the front and back panels 10 and 20 are sealed. In the sealing, gas is being exhausted from the envelope 40 by the turbo-molecule pump 53b. Note that when the turbo-molecule pump 53b is actuated, the rotary pump 53c 10 is simultaneously actuated to lower the back pressure in the turbo-molecule pump 53b. The condition for sealing is determined by the compatibility between the material of the glass plates and the sealant. When the low melting point glass is used, the sealing condition is 15 approximately 10 to 20 minutes around 450°C.

It is preferable to start the exhaust after the temperature in the heating furnace 51 reaches the softening temperature of the sealant. Before the temperature reaches the softening temperature, the 20 airtightness of the outer edges of the front and back panels 10 and 20 is not high enough to produce a high vacuum in the envelope 40 even if gas is exhausted from the envelope 40. On the other hand, after the sealant is softened, the apertures between the front and back panels 25 10 and 20 along the outer edges are sealed. Also, the bonding member 55a is softened to seal the apertures

between the connecting tube 55 and the ventilation slot.

21a. As a result, when the gas is exhausted from the envelope 40, the pressure is reduced to produce a high vacuum (approximately 1.33×10^{-4} MPa, i.e., approximately several Torr).

By exhausting gas from the envelope 40 as has been described, pressure is evenly applied to the front and back panels 10 and 20 from the outside. The degree of suction and exhaust by the suction exhaust system 53 is enough when the sealant is pressed to shrink due to the difference between the pressures in the envelope 40 and in the heating furnace and the front and back panels come to closer to each other so that the front panel touches the partition walls. For this reason, the suction and exhaust is slightly performed (for instance, approximately 0.08 MPa).

When pressure is evenly applied to the front and back panels 10 and 20 from the outside, the front panel 10 comes into contact with the top ends of the partition walls on the back panel 20 as shown in Fig. 3. When the temperature is lowered in this state, the temperature of the sealant becomes lower than the softening temperature and the sealant hardens to seal the envelope 40. As a result, the front panel 10 and the entire top ends of the partition walls are kept in absolute contact in the sealed envelope 40.

Note that the temperature is increased not at one stroke to the sealing temperature that is slightly higher than the softening temperature of the sealant in the sealing process. The temperature is kept at lower than 5 the sealing temperature for a certain period of time, for instance, at around 350°C for 30 minutes, to burn out the binder material. This is effective at preventing the phosphor from deteriorating.

When the envelope 40 is sealed as has been 10 described, the next processing advances to the vacuum pumping process.

In the vacuum pumping process, the inside of the heating furnace 51 is heated (baked) at a temperature (exhaust baking temperature) that is lower than the 15 softening temperature of the sealant layer. In this heating, the open/close valve 53f is opened at an appropriate degree, and the turbo-molecule pump 53b and the rotary pump 53c are actuated so as to evacuate the envelope 40. Then, the discharge gas is introduced into 20 the envelope 40 from the gas introducing system 52 with a predetermined pressure (for instance, 0.05MPa). It is preferable to keep the pressure for a predetermined period of time (5 to 10 minutes) after the envelope 40 is filled with the discharge gas. This is because it takes 25 a certain period of time to reach the equilibrium pressure since the conductance between the partition

walls in the envelope is small.

Note that it is preferable to perform the vacuum pumping process at the baking temperature as has been described since the impurity that has been absorbed into the interior wall of the envelope 40 tends to fill the discharge space in gaseous form. In this situation, the impurity can be expelled from the envelope more swiftly. For this reason, the evacuation is generally performed at the exhaust baking temperature. The evacuation, however, is not limited to this case. Merely the evacuation can be performed.

Also, the exhaust baking temperature is lower than the softening temperature of the sealant. When a metal is used as the sealant, the softening temperature is lower than the melting point of the metal. Here, the exhaust baking temperature is a temperature that is effective at removing the absorbed water that has been absorbed into the interior wall of the envelope 40 (for instance, around 350°C).

The vacuum pumping process can start after the temperature of the envelope 40 is lowered to the room temperature. It is preferable, however, to start the vacuum pumping process when the sealing temperature in the sealing process is lowered to the exhaust baking temperature. This is because the manufacturing process can be shortened since the period of time to re-increase

the lowered temperature to the exhaust baking temperature is saved.

Then, the discharge gas introduction from the gas introducing system 52 is stopped and the discharge gas is 5 sucked out from the envelope with the suction exhaust system 53 to re-establish a vacuum state in the envelope 40 again.

Usually, it is enough to perform a series of processes of vacuum pumping, discharge gas introduction, 10 and vacuum pumping only once. When the series of processes is repeated, however, the impurity gas concentration is further lowered in the envelope 40.

Here, the gas introduced into the envelope 40 is not limited to discharge gas. Any kind of gas can be 15 used as long as the gas is not any impurity gas for the discharge gas. Not clearly defined, the impurity is a kind of gas that lowers the intensity. Also, it is preferable that the gas to be introduced is a dry gas since the phosphor is prevented from deteriorating. 20 Here, the dry gas is a gas that has a partial pressure of water vapor lower than the ordinary gas. For instance, the partial pressure of water vapor (dew point) is no higher than 0.0027MPa (22°C).

The pressure that is to be introduced into the 25 envelope 40 after evacuation can be from around 1.33×10^{-4} MPa (several Torr) to the maximum pressure with which

the envelope 40 is not broken. It is preferable that the pressure is lower than the atmospheric pressure.

The next process is the discharge gas filling process. In the discharge gas filling process, the discharge gas is supplied to the internal space of the envelope 40 by the gas introducing system 52 so as to have a predetermined pressure for filling (for instance, 0.067MPa). Then, the connecting tubes 55 and 56 are molten with a burner or a heater where the connecting tubes 55 and 56 are fixed to the back panel 20 to be sealed off (chipped off). As a result, the ventilation slots 21a and 21b are sealed.

[Effects of Producing Method of the First Embodiment]

When the pressure is set to be the same inside and outside of the envelope 40 and the envelope 40 is tightly held along the outer edge as in the case of the conventional producing method, pressure is not applied to the central parts of the front and panel of the envelope 40. As a result, a part or the entire part of the top ends of the partition walls on the back panel 20 tends not to come in contact with the front panel 10 when the envelope 40 is sealed. On the other hand, the sealant layer 41 is hardened to seal the envelope 40 while pressure is evenly applied to the front and back panels 10 and 20 from the outside as has been described in the

present embodiment. As a result, the front panel 10 almost comes into contact with the top ends of the partition walls when the envelope 40 is sealed.

Accordingly, it is easy to produce a PDP with 5 rare vibration at the time of drive and with excellent display quality according to the producing method of the present embodiment.

In order to obtain these effects, it is at least necessary to actuate the suction exhaust system so as to 10 set the pressures inside and outside of the envelope to be different when the softened sealant layer 41 is hardened. It is not necessary, however, to successively actuate the suction exhaust system 53 from the start to the end of the sealing process. For instance, when the 15 suction exhaust system 53 starts to be actuated after the sealant layer 41 is softened, the effects due to the pressure difference between the inside and outside of the front and back panels 10 and 20 can be sufficiently obtained.

20 Also, as a result of the vacuum pumping process, the impurity gas concentration can be swiftly lowered.

This can be a result of 1) the effect of diluting 25 impurity gas by filling the envelope with a large amount of discharge gas, 2) the effect of exhausting residual impurity gas from the envelope 40 by the viscous flow at the time of the gas filling and gas re-exhausting, 3) the

effect of removing absorbed gas by collision of discharge gas molecules with the internal wall of the envelope 40 such as the phosphors and the protection layer, and the like. According to the third effect, it is preferable to 5 use a gas that has been heated as the discharge gas (cleaning gas) to be introduced into the envelope in the vacuum pumping process.

After the envelope 40 is evacuated while the temperature is kept at the exhaust baking temperature, 10 the residual gas in the discharge space surrounded by the partition walls is not sufficiently exhausted from the envelope 40. For instance, suppose that the height of the partition walls in the envelope 40 is 120 μm , the pitch between the partition walls is 200 μm , the diameter of the slot for exhaust is approximately 2mm, the 15 internal diameter of the connecting tube 56 is approximately 2mm, and the length of the connecting tube 56 is approximately 90mm. In this case, when the gas is exhausted at the exhaust baking temperature of 350°C, the pressure inside of the envelope 40 is 10 to 20 times the 20 pressure inside of the manifold 53a even if the pressure inside of the manifold 53a is approximately 1.3×10^{-11} to 1.3×10^{-10} MPa.

Of course, when the period of time for baking is 25 lengthened, the amount of water and impurity gas that have been absorbed into the interior wall of the envelope

40 is reduced. The manufacturing cost is instead raised.

In the vacuum pumping process that has been described, after filled with the discharge gas, the envelope 40 is evacuated again. The impurity gas can be
5 removed more swiftly according to the method described below.

While the envelope 40 is being filled with the discharge gas introduced by the gas introducing system 52, the discharge gas is exhausted from the envelope 40
10 with the suction exhaust system 53. The flow of the discharge gas is shown by large arrows in Fig. 3(a). By doing so, the discharge gas flows in the envelope 40, so
that the impurity gas can be removed more efficiently. Especially, the impurity gas in the discharge space apart
15 from the exhaust hole (the ventilation slot 21b) is effectively exhausted from the innermost part in the envelope 40.

In this case, it is possible to fill the envelope 40 with the discharge gas without evacuating the envelope
20 40 before the filling process.

(The First Practical Example)

A specific explanation of the first practical example of the PDP producing method in which each of the
25 processes is performed according to the first preferred embodiment will be given below.

Fig. 4 shows temperature and pressure profiles during sealing. Fig. 5 shows temperature and pressure profiles in an vacuum pumping/filling process. In the first practical example, the PDP is manufactured according to each of the profiles. Note that the dotted line in Figs. 4 and 5 shows the temperature of the envelope 40 while the solid line the pressure change in the manifold 53a.

The sealing process will be explained first. The temperature is increased to the sealing temperature, 450°C in two to three hours, and the sealing temperature is kept for about 20 minutes. Meanwhile, when the temperature reaches 450°C, the pressure in the manifold 53a is lowered to around 0.05MPa and the suction exhaust system is stopped and remains stopped.

Then, while the lowered pressure is kept, the temperature is decreased to the room temperature in two to three hours.

At this stage, the front and back panels have been sealed.

Next, as shown in Fig. 5, the evacuation is continued and heating is started after the pressure in the manifold 53a becomes around 1.3×10^{-11} to 1.3×10^{-10} MPa. The temperature is increased to the exhaust baking temperature (350°C) in two to three hours. When the temperature reaches the exhaust baking temperature, the

evacuation is started again to exhaust the gas that has circulated into the manifold during the temperature increase. When the evacuation is resumed, the pressure in the manifold 53a rises as indicated by an arrow 60 in Fig. 5 due to the gas removed from the interior walls of the connecting tube 56 and the envelope 40. At the start of the evacuation, however, the pressure begins lowering.

Then, when the pressure in the manifold 53a reaches around 1.3×10^{-11} to 1.3×10^{-10} MPa, the suction exhaust system 53 stops and the gas introducing system 52 is actuated. The envelope 40 is filled with the discharge gas with around 0.05MPa of pressure and the pressure is kept for five to 10 minutes.

After that, in the course of cooling, gas starts to be evacuated from the envelope 40. After the pressure reaches around 1.3×10^{-11} to 1.3×10^{-10} , the gas introducing system 52 fills the envelope 40 with the discharge gas with 0.067MPa of pressure.

In the conventional vacuum pumping process, it takes around two hours to lower the pressure in the envelope to 1.3×10^{-11} to 1.3×10^{-10} . On the other hand, pressure can be lowered more swiftly in the vacuum pumping process of the first practical example. More specifically, it takes about one hour.

Here, the pressure can be lowered in a short period of time by increasing the driving force of the

pump system of the suction exhaust system and evacuating the envelope more powerfully. In this case, however, the phosphors in the envelope come off the phosphor layers, for instance, leading to panel property deterioration.

5 For this reason, the manifold is disposed as has been described to weaken the force of suction to evacuate the envelope. As a result, it takes a relatively long period of time to lower the pressure in the envelope in the conventional vacuum pumping process.

10 For the PDP that has been produced according to the above-mentioned method, lifting rarely occurs in the outer regions. Also, the discharge properties are even compared with the conventional method in which pressure is applied only with clips. The level of noise from the outer regions is reduced by approximately several to 15 10db. The voltage at the start of discharge decreases by approximately 5 to 10V. Furthermore, the discharge current decreases by approximately several to 10% and the effectiveness improves by around 10%.

20

(The Second Practical Example)

An explanation of the second practical example of the PDP producing method in which each of the processes is performed according to the first preferred embodiment 25 will be given below.

Fig. 6 shows temperature and pressure profiles

5 during the sealing and in the vacuum pumping/filling process. In the second practical example, the PDP is produced according to the profiles. Note that dotted line in Fig. 6 shows the temperature of the envelope 40 while the solid line the pressure change in the manifold of the suction exhaust system connected to the envelope 40.

10 The sealing process will be explained first. The temperature is increased to the sealing temperature, 450°C in two to three hours, and the sealing temperature is kept for about 20 minutes. Meanwhile, when the temperature reaches 450°C, the pressure in the manifold 53a is lowered to around 0.05MPa and the suction exhaust system is stopped and remains stopped.

15 Then, while the lowered pressure is kept, the temperature is decreased to the exhaust baking temperature (350°C) in 30 minutes.

20 At this stage, the front and back panels have been sealed. When the pressure in the manifold 53a is monitored as the temperature is decreased, defective sealing can be detected and dealt with in the early stage of the producing process to help lower the cost.

25 Next, after the temperature is decreased to the exhaust baking temperature, the evacuation is continued to lower the pressure in the manifold 53a to 1.3×10^{-11} to 1.3×10^{-10} MPa. Then, the suction exhaust system 53 is

stopped and the gas introducing system 52 is actuated to fill the envelope 40 with the discharge gas with 1.15MPa of pressure. The pressure is kept for five to 10 minutes.

5 After that, in the course of cooling, gas starts to be evacuated from the envelope 40. After the pressure reaches around 1.3×10^{-11} to 1.3×10^{-10} , the gas introducing system 52 fills the envelope 40 with the discharge gas with 0.067MPa of pressure.

10 In the conventional vacuum pumping process, it takes around two hours to lower the pressure in the envelope to 1.3×10^{-11} to 1.3×10^{-10} . On the other hand, pressure can be lowered more swiftly in the vacuum pumping process according to the first embodiment. More 15 specifically, it takes about one hour.

For the PDP that has been produced according to the above-mentioned method, lifting rarely occurs in the outer regions. Also, the discharge properties are even compared with the conventional method in which pressure 20 is applied only with clips. The level of noise from the outer regions is reduced by approximately several to 10db. The voltage at the start of discharge decreases by approximately 5 to 10V. Furthermore, the discharge current decreases by approximately several to 10% and the 25 effectiveness improves by around 10%.

Compared with the first practical example, the

producing method in the second practical example is effective at shortening the period of time from the sealing to the cooling of the envelope 40 and the period of time for heating from the room temperature to the 5 exhaust baking temperature. Also, the phosphor deteriorates less than the first practical example by several percent or so. The quality is slightly better than the first practical example.

10 (The Second Embodiment)

The second embodiment is different from the first embodiment in the method in the vacuum pumping process.

Fig. 7 is a diagrammatic sketch of a sealing/exhausting device 70 used in the sealing process of the second embodiment. Fig. 7 corresponds to Fig. 15 3(b).

The sealing/exhausting device 70 encloses the envelope 40, which is formed by providing the front panel 10 on the back panel 20. Also, the sealing/exhausting 20 device 70 includes a heating furnace 71 for heating the envelope 40 and a gas introducing/suction exhaust system 72 that is provided outside of the heating furnace 71.

To the back panel 20, a connecting tube 73 and a getter tube 74 are tentatively fastened via bonding 25 members 73a and 74a so as to connect the ventilation slots 21a and 21b to the internal space, respectively as

in the case of the first embodiment.

The connecting tube 73 is a glass tube that connects to the back panel 20 with an open end. The getter tube 74 is a glass tube that connects to the back panel 20 with a sealed end. At the end of the getter tube 74 corresponding to the exit of the ventilation slot 21b in the back panel 20, a getter enclosing space 74b is formed for enclosing a getter.

The gas introducing/suction exhaust system 72 includes a manifold 72a, a turbo-molecule pump 72b, a rotary pump 72c, a gas bomb 72d, a pipe system 72e, and a branch connection system 72f. The gas bomb 72d is filled with the discharge gas. The pipe system 72e connects the connecting tube 73 to the manifold 72a. The branch connection system 72f connects the manifold 72a to the turbo-molecule pump 72b and the gas bomb 72d. In the branch connection system 72f, a connection system 72f1 from the manifold 72a branches into connection systems 72f2 and 72f3 via a channel selection valve 72g. The connection systems 72f2 and 72f3 are connected to the turbo-molecule pump 72b and the gas bomb 72d, respectively. In the midst of the connection systems 72f2 and 72f3, open/close valves 72h and 72i are disposed. While the open/close valve 72h adjusts the amount of gas sucked out by the turbo-molecule pump, the 72i open/close valve adjusts the amount of flow of

discharge gas. The connecting tube 73 and the pipe system 72e are connected to each other with a chuck so as to ensure airtightness. The channel selection valve 72g selects the connection system 72f2 when the turbo-
5 molecule pump 72b is actuated. On the other hand, the connection system 72f3 is selected when the discharge gas is introduced into the envelope 40 from the gas bomb 72d.

Then, the temperature in the heating furnace 71 is increased to a sealing temperature (for instance, 10 450°C) that is slightly higher than the softening temperature of the sealant by a heater 75. After kept at the sealing temperature for a certain period of time, the temperature is decreased lower than the softening temperature. By doing so, the apertures between the front and back panels 10 and 20 are sealed. In the sealing, the envelope 40 is evacuated by the turbo-
15 molecule pump 72b from the inside. The condition for sealing is determined by the compatibility between the material of the glass plates and the sealant. When the 20 low melting point glass is used, the sealing condition is approximately 10 to 20 minutes around 450°C.

It is preferable to start the exhaust after the temperature in the heating furnace 71 reaches the softening temperature of the sealant. Before the 25 temperature reaches the softening temperature, the airtightness of the outer edges of the front and back

panels 10 and 20 is not high enough to produce a high vacuum in the envelope 40 even if gas is exhausted from the envelope 40. On the other hand, after the sealant is softened, the apertures between the front and back panels 5 10 and 20 along the outer edges are sealed. Also, the sealant layer 41 is softened to seal the apertures between the connecting tube 72 and the ventilation slot 21a. As a result, when the gas is exhausted from the envelope 40, the pressure is reduced to produce a high 10 vacuum (approximately 1.33×10^{-4} MPa, i.e., approximately several Torr).

By exhausting gas from the envelope 40 as has been described, pressure is evenly applied to the front and back panels 10 and 20 from the outside. The degree of suction and exhaust is enough when the sealant is 15 pressed to shrink due to the difference between the pressures in the envelope 40 and in the heating furnace and the front and back panels come to closer to each other so that the front panel touches the partition 20 walls. For this reason, the suction and exhaust is slightly performed (for instance, approximately 0.08MPa).

When pressure is evenly applied to the front and back panels 10 and 20 from the outside, the front panel 10 comes into contact with the top ends of the partition 25 walls on the back panel 20 as has been described. When the temperature is lowered in this state, the temperature

of the sealant becomes lower than the softening temperature and the sealant hardens to seal the envelope 40. As a result, the front panel 10 and the entire top ends of the partition walls are kept in absolute contact 5 in the sealed envelope 40.

Next, after the temperature is lowered to the room temperature, an end 74c of the getter tube 74 is broken to insert getter 76. The amount of the getter 76 corresponds to the size of the internal space of the envelope 40. Then, the end 74c is sealed off to enclose the getter 76 into the getter enclosing space 74b. The getter 76 can be a substance the surface of which is activated by heating to irreversibly, chemically absorb the impurity gas. In this case, it is preferable to use a substance that is chemically activated at the exhaust baking temperature later in the vacuum pumping process.

Then, after a vacuum state is re-established in the envelope 40, heating (baking) is started when the temperature in the heating furnace 71 is lower than the softening temperature of the sealant layer (at the exhaust baking temperature).

Also, the exhaust baking temperature is lower than the softening temperature of the sealant. When a metal is used as the sealant, the softening temperature 25 is lower than the melting point of the metal. Here, the exhaust baking temperature is a temperature that

activates the getter 76 and is effective at removing the absorbed water that has been absorbed into the interior wall of the envelope 40 (for instance, around 350°C).

When the temperature reaches the temperature for activating the getter 76 during the temperature increase to the exhaust baking temperature, water and impurity gas such as carbon dioxide, nitrogen, oxygen, and so on are absorbed to the surface of the particle of the getter 76.

The absorbed water and impurity gas is taken in the particle pores. This is because of the pressure gradient (gas concentration gradient) between the internal space of the envelope 40 and the getter enclosing space 74b, into which the getter 76 is enclosed, as a result that the impurity gas is taken in the getter 76.

Then, while the temperature is kept at the exhaust baking temperature, the open/close valve 72h is opened to an appropriate degree and the turbo-molecule pump 72b and the rotary pump 72c are activated to further evacuate the envelope 40. After that, the connection system 72f3 is selected with the channel selection valve 72g and the open/close valve 72i is opened to introduce the discharge gas into the envelope 40 with a predetermine pressure (for instance, 0.05MPa). It is more preferable to keep the pressure for a predetermined period of time (five to 10 minutes) after the envelope 40 is filled with the discharge gas. This is because it

takes a certain period of time to reach the equilibrium pressure since the conductance between the partition walls in the envelope 40 is small.

Then, the discharge gas introduction is stopped
5 and the discharge gas is sucked out from the envelope to re-establish a vacuum state in the envelope 40 again.

Usually, it is enough to perform a series of processes of vacuum pumping, discharge gas introduction, and vacuum pumping only once. When the series of
10 processes is repeated, however, the impurity gas concentration is further lowered in the envelope 40.

Here, the gas introduced into the envelope 40 is not limited to discharge gas. Any kind of gas can be used as long as the gas is not impurity for discharge gas. Also, it is preferable that the gas to be introduced is a dry gas since the phosphor is prevented
15 from deteriorating.

The pressure that is to be introduced into the envelope 40 after evacuation can be from around 1.33×10^{-4} MPa (several Torr) to the maximum pressure with which the envelope 40 is not broken. It is preferable that the pressure is lower than the atmospheric pressure.

The next process is the discharge gas filling process. In the discharge gas filling process, the
25 discharge gas is supplied to the internal space of the envelope 40 so as to have a predetermined pressure for

filling (for instance, 0.067MPa). Then, the connecting tubes 73 and the getter tube 74 are molten with a burner or a heater where the connecting tubes 55 and 56 are fixed to the back panel 20 to be sealed off (chipped off). As a result, the ventilation slots 21a and 21b are sealed.

[Effects of Producing Method of the Second Embodiment]

When the pressure is set to be the same inside and outside of the envelope 40 and the envelope 40 is tightly held along the outer edge as in the case of the conventional producing method, pressure is not applied to the central parts of the front and back panels of the envelope 40. As a result, a part or the entire part of the top ends of the partition walls on the back panel 20 tends not to come in contact with the front panel 10 when the envelope 40 is sealed. On the other hand, the sealant layer 41 is hardened to seal the envelope 40 while pressure is evenly applied to the front and back panels 10 and 20 from the outside as has been described in the present embodiment. As a result, the front panel 10 almost comes into contact with the top ends of the partition walls when the envelope 40 is sealed.

Accordingly, it is easy to produce a PDP with rare vibration at the time of drive and with excellent display quality according to the producing method of the

present embodiment.

In order to obtain these effects, it is at least necessary to actuate the suction exhaust system so as to set the pressures inside and outside of the envelope to be different when the softened sealant layer 41 is hardened. It is not necessary, however, to successively evacuate the envelope 40 from the start to the end of the sealing process. For instance, when the envelope 40 starts to be evacuated after the sealant layer 41 is softened, the effects due to the pressure difference between the inside and outside of the front and back panels 10 and 20 can be sufficiently obtained.

Also, as a result of the vacuum pumping process, the impurity gas concentration can be swiftly lowered.

This can be a result of 1) the effect of diluting impurity gas by filling the envelope with a large amount of discharge gas, 2) the effect of exhausting residual impurity gas from the envelope 40 by the viscous flow at the time of the gas filling and gas re-exhausting, 3) the effect of removing absorbed gas by collision of discharge gas molecules with the internal wall of the envelope 40 such as the phosphors and the protection layer, and the like. According to the third effect, it is preferable to use a gas that has been heated as the discharge gas (cleaning gas) to be introduced into the envelope in the vacuum pumping process.

Also, in the present embodiment, the process for removing impurity gas in the envelope with the getter is included in the step to increase the temperature to the exhaust baking temperature. As a result, impurity gas 5 can be removed more swiftly and the impurity gas concentration can be further lowered compared with the producing method in the first embodiment, in which only the series of processes of vacuum pumping, discharge gas introduction, and vacuum pumping is performed.

10

(The Third Practical Example)

A specific explanation of the third practical example of the PDP producing method in which each of the processes is performed according to the first preferred embodiment will be given below. 15

15

In the third practical example, the PDP is manufactured according to each of the profiles shown in Figs. 4 and 5. The getter 76 is inserted into the getter tube 74 when the sealing has been performed and the 20 temperature has been lowered to the room temperature. As the getter, vanadium, titanium, and iron alloy particles that are activated at 280°C are used.

20

In the conventional vacuum pumping process, it takes around two hours to lower the pressure in the 25 envelope to 1.3×10^{-11} to 1.3×10^{-10} . On the other hand, pressure can be lowered in around one hour in the vacuum

pumping process of the third practical example.

For the PDP that has been produced according to the above-mentioned method, lifting rarely occurs in the outer regions. Also, the discharge properties are even 5 compared with the conventional method in which pressure is applied only with clips. The level of noise from the outer regions is reduced by approximately several to 10db. The voltage at the start of discharge decreases by approximately 5 to 10V. Furthermore, the discharge 10 current decreases by approximately several to 10% and the effectiveness improves by around 10%.

Compared with the first practical example, properties slightly less deteriorates after an aging process (i.e., a process for stabilizing the panel 15 properties after the discharge gas filling process) in the producing method in the third practical example. Also, the producing method is more effective by several percent.

20 (The Third Embodiment)

The third embodiment is different from the first embodiment in the method in the sealing process.

First, the temperature in the heating furnace 51 is increased to the sealing temperature that is slightly 25 higher than the softening temperature of the sealant (for instance, 450°C). After kept at the sealing temperature

for a predetermined period of time, the temperature is decreased lower than the softening temperature. By doing so, the apertures between the front and back panels 10 and 20 are sealed. While the temperature is increased to 5 the sealing temperature, the gas introducing system is actuated to introduce dry gas into the envelope 40. Note that dried discharge gas with which the gas bomb 52a is charged is used as the dry gas in the third embodiment. Also, dry air, dry nitrogen gas, dry argon gas, dry neon 10 gas (all referred to as noble gas) can be used as the dry gas. When the temperature reaches the sealing temperature, the sealant is softened to ensure the airtightness of the envelope 40. As a result, the internal pressure of the envelope 40 is increased. When 15 the internal pressure increase is monitored, the introduction of the discharge gas is stopped.

Note that the amount of dry gas is limited so that the glass plates of the envelope 40 are not broken due to sharp pressure increase even if the dry gas flows 20 into the envelope 40 when the sealant is softened to seal the envelope 40.

As has been described, the dry gas is composite through the envelope 40 until the temperature reaches the sealing temperature. As a result, when the envelope 40 25 has been sealed by softened sealant, the envelope 40 is filled with the dry gas. Then, the temperature is kept

at the sealing temperature for a predetermined period of time. The condition for sealing is determined by the compatibility between the material of the glass plates and the sealant. When the low melting point glass is used, the sealing condition is approximately 10 to 20 minutes around 450°C.

In this way, the envelope 40 is sealed while the envelope 40 is filled with the dry gas. By doing so, heat deterioration of the phosphors is prevented.

Furthermore, the temperature is kept at the sealing temperature while the envelope is filled with the dry gas. At the same time, the sealing is performed while the envelope is evacuated with the turbo-molecule pump 53b. Note that when the turbo-molecule pump 53b is activated, the rotary pump 53c is also activated to lower the back pressure in the turbo-molecule pump 53b.

It is preferable to start the exhaust after the temperature in the heating furnace 51 reaches the softening temperature of the sealant.. Before the temperature reaches the softening temperature, the airtightness of the outer edges of the front and back panels 10 and 20 is not high enough to produce a high vacuum in the envelope 40 even if gas is exhausted from the envelope 40. On the other hand, after the sealant is softened, the apertures between the front and back panels 10 and 20 along the outer edges are sealed. Also, the

bonding member 56a is softened to seal the apertures between the connecting tube 56 and the ventilation slot 21b. As a result, when the gas is exhausted from the envelope 40, the pressure is reduced to produce a high 5 vacuum (approximately 1.33×10^{-4} MPa, i.e., approximately several Torr).

By exhausting gas from the envelope 40 as has been described, pressure is evenly applied to the front and back panels 10 and 20 from the outside. The degree 10 of suction and exhaust is enough when the sealant is pressed to shrink due to the difference between the pressures in the envelope 40 and in the heating furnace and the front and back panels come to closer to each other so that the front panel touches the partition 15 walls. For this reason, the suction and exhaust is slightly performed (for instance, approximately 0.08MPa).

When pressure is evenly applied to the front and back panels 10 and 20 from the outside, the front panel 10 comes into contact with the top ends of the partition walls on the back panel 20 as shown in Fig. 3. When the 20 temperature is lowered in this state, the temperature of the sealant becomes lower than the softening temperature and the sealant hardens to seal the envelope 40. As a result, the front panel 10 and the entire top ends of the 25 partition walls are kept in absolute contact in the sealed envelope 40.

Note that the temperature is increased not at one stroke to the sealing temperature that is slightly higher than the softening temperature of the sealant in the sealing process. The temperature is kept at lower than 5 the sealing temperature for a certain period of time, for instance, at around 350°C for 30 minutes, to burn out the binder material. This is effective at preventing the phosphor from deteriorating.

After the sealing process, the processing 10 advances to the vacuum pumping process, the sealing process, and the discharge gas filling process to produce the PDP as in the case of the first embodiment.

(The Fourth Practical Example)

A specific explanation of the fourth practical 15 example of the PDP producing method in which each of the processes is performed according to the third preferred embodiment will be given below.

In the fourth practical example, the PDP is 20 manufactured according to each of the profiles shown in Figs. 4 and 5.

The sealing process will be explained first. The temperature is increased to the sealing temperature, 450°C in two to three hours, and the sealing temperature 25 is kept for about 20 minutes. Meanwhile, the dry gas is composite through the envelope 40 by activating the gas

introducing system until the temperature reaches the sealing temperature.

Then, when the temperature reaches 450°C, the gas introducing system is stopped and the pressure in the 5 manifold is lowered to and kept around 0.05MPa.

Next, while the lowered pressure is kept, the temperature is decreased to the room temperature in two to three hours.

At this stage, the front and back panels have 10 been sealed. When the pressure in the manifold is monitored as the temperature is decreased, defective sealing can be detected and dealt with in the early stage of the producing process to help lower the cost. The pressure in the manifold gradually drops when the sealing 15 is normally performed. If the sealing is not normally performed, however, gas is leaked into the heating furnace, so that the pressure drops at a relatively high speed.

Next, as shown in Fig. 5, the evacuation is 20 continued and heating is started after the pressure in the manifold 53a becomes around 1.3×10^{-11} to 1.3×10^{-10} MPa. The temperature is increased to the exhaust baking temperature (350°C) in two to three hours. When the temperature reaches the exhaust baking temperature, the 25 evacuation is started again to exhaust the gas that has flowed into the manifold during the temperature increase.

When the evacuation is resumed, the pressure in the manifold 53a rises as indicated by an arrow 60 in Fig. 5 due to the gas removed from the interior walls of the connecting tube and the envelope 40. At the start of the 5 evacuation, however, the pressure begins lowering.

Then, when the pressure in the manifold 53a reaches around 1.3×10^{-11} to 1.3×10^{-10} MPa, the suction exhaust system 53 stops and the gas introducing system 52 is actuated. The envelope 40 is filled with the 10 discharge gas with around 0.05MPa of pressure and the pressure is kept for five to 10 minutes.

After that, in the course of cooling, gas starts to be evacuated from the envelope 40. After the pressure reaches around 1.3×10^{-11} to 1.3×10^{-10} , the gas introducing system 52 fills the envelope 40 with the discharge gas 15 with 0.067MPa of pressure.

In the conventional vacuum pumping process, it takes around two hours to lower the pressure in the envelope to 1.3×10^{-11} to 1.3×10^{-10} . On the other hand, 20 pressure can be lowered in about one hour in the vacuum pumping process of the fourth practical example.

For the PDP that has been produced according to the above-mentioned method, lifting rarely occurs in the outer regions. Also, the discharge properties are even 25 compared with the conventional method in which pressure is applied only with clips. The level of noise from the

outer regions is reduced by approximately several to 10db. The voltage at the start of discharge decreases by approximately 5 to 10V. Furthermore, the discharge current decreases by approximately several to 10% and the 5 effectiveness improves by around 10%.

Meanwhile, a comparative evaluation of the luminescence intensity (intensity/"y" chromaticity coordinate value) is performed on the phosphors of the PDP that has been sealed after dry gas is circulated as 10 has been described and the PDP that has been sealed while the atmosphere is included in the PDP according to the conventional method. The comparative evaluation is performed by breaking the panel and irradiate Xe excimer lamp (with 173nm of wavelength). The luminescence 15 intensity is improved by around 10% for the blue phosphor. Although the luminescence intensity is improved for all kinds of non-reactive dry gas, significantly improved for dry air.

20 (The Fifth Practical Example)

A specific explanation of the fifth practical example of the PDP producing method in which each of the processes is performed according to the third preferred embodiment will be given below.

25 In the fifth practical example, the PDP is manufactured according to each of the profiles shown in

Fig. 6.

The sealing process will be explained first. The temperature is increased to the sealing temperature, 450°C in two to three hours, and the sealing temperature 5 is kept for about 20 minutes. Meanwhile, the dry gas is circulated through the envelope 40 by activating the gas introducing system until the temperature reaches the sealing temperature.

Then, when the temperature reaches 450°C, the gas 10 introducing system is stopped and the pressure in the manifold is lowered to and kept around 0.05MPa.

Next, while the lowered pressure is kept, the temperature is decreased to the exhaust baking 15 temperature (350°C) in around 30 minutes.

At this stage, the front and back panels have been sealed. When the pressure in the manifold is monitored as the temperature is decreased, defective sealing can be detected and dealt with in the early stage 20 of the producing process to help lower the cost.. The pressure in the manifold gradually drops when the sealing is normally performed. If the sealing is not normally performed, however, gas is leaked into the heating furnace, so that the pressure drops at a relatively high speed.

25 Next, after the temperature is decreased to the exhaust baking temperature, the evacuation is continued

to lower the pressure in the manifold to 1.3×10^{-11} to 1.3×10^{-10} MPa. Then, the suction exhaust system 53 is stopped and the gas introducing system 52 is actuated to fill the envelope 40 with the discharge gas with 1.15MPa of pressure. The pressure is kept for five to 10 minutes.

After that, in the course of cooling, gas starts to be evacuated from the envelope 40. After the pressure reaches around 1.3×10^{-11} to 1.3×10^{-10} , the gas introducing system fills the envelope 40 with the discharge gas with 0.067MPa of pressure.

In the conventional vacuum pumping process, it takes around two hours to lower the pressure in the envelope to 1.3×10^{-11} to 1.3×10^{-10} . On the other hand, pressure can be lowered more swiftly in the vacuum pumping process according to the first embodiment. More specifically, it takes about one hour.

For the PDP that has been produced according to the above-mentioned method, lifting rarely occurs in the outer regions. Also, the discharge properties are even compared with the conventional method in which pressure is applied only with clips. The level of noise from the outer regions is reduced by approximately several to 10db. The voltage at the start of discharge decreases by approximately 5 to 10V. Furthermore, the discharge current decreases by approximately several to 10% and the

effectiveness improves by around 10%.

Compared with the fourth practical example, the producing method in the fifth practical example is effective at shortening the period of time from the 5 sealing to the cooling of the envelope 40 and the period of time for heating from the room temperature to the exhaust baking temperature. Also, the phosphor deteriorates less than the first practical example by several percent or so. The quality is slightly better 10 than the fourth practical example.

(The Fourth Embodiment)

The fourth embodiment is different from the second embodiment in the method in the sealing process.

First, the temperature in the heating furnace 71 is increased to the sealing temperature that is slightly higher than the softening temperature of the sealant (for instance, 450°C). After kept at the sealing temperature for a predetermined period of time, the temperature is 15 decreased lower than the softening temperature. By doing 20 so, the apertures between the front and back panels 10 and 20 are sealed. While the temperature is increased to the sealing temperature, the gas introducing system is actuated to introduce dry gas into the envelope 40. Note 25 that dried discharge gas with which the gas bomb 72d is charged is used as the dry gas in the third embodiment.

Also, dry air, dry nitrogen gas, dry argon gas, dry neon gas (all referred to as noble gas) can be used as the dry gas. When the temperature reaches the sealing temperature, the sealant is softened to ensure the airtightness of the envelope 40. As a result, the internal pressure of the envelope 40 is increased. When the internal pressure increase is monitored, the introduction of the discharge gas is stopped.

Note that the amount of dry gas is limited so that the glass plates of the envelope 40 are not broken due to sharp pressure increase even if the dry gas flows into the envelope 40 when the sealant is softened to seal the envelope 40.

As has been described, the dry gas is circulated through the envelope 40 until the temperature reaches the sealing temperature. As a result, when the envelope 40 has been sealed by softened sealant, the envelope 40 is filled with the dry gas. Then, the temperature is kept at the sealing temperature for a predetermined period of time. The condition for sealing is determined by the compatibility between the material of the glass plates and the sealant. When the low melting point glass is used, the sealing condition is approximately 10 to 20 minutes around 450°C.

In this way, the envelope 40 is sealed while the envelope 40 is filled with the dry gas. By doing so,

heat deterioration of the phosphors is prevented.

Furthermore, the temperature is kept at the sealing temperature while the envelope is filled with the dry gas. At the same time, the sealing is performed 5 while the envelope is evacuated with the turbo-molecule pump 72b. Note that when the turbo-molecule pump 72b is activated, the rotary pump 72c is also activated to lower the back pressure in the turbo-molecule pump 72b.

It is preferable to start the exhaust after the 10 temperature in the heating furnace 71 reaches the softening temperature of the sealant. Before the temperature reaches the softening temperature, the airtightness of the outer edges of the front and back panels 10 and 20 is not high enough to produce a high 15 vacuum in the envelope 40 even if gas is exhausted from the envelope 40. On the other hand, after the sealant is softened, the apertures between the front and back panels 10 and 20 along the outer edges are sealed. Also, the bonding member 73a is softened to seal the apertures 20 between the connecting tube 73 and the ventilation slot 21a. As a result, when the gas is exhausted from the envelope 40, the pressure is reduced to produce a high vacuum (approximately 1.33×10^{-4} MPa, i.e., approximately several Torr).

25 By exhausting gas from the envelope 40 as has been described, pressure is evenly applied to the front

and back panels 10 and 20 from the outside. The degree of suction and exhaust is enough when the sealant is pressed to shrink due to the difference between the pressures in the envelope 40 and in the heating furnace 5 and the front and back panels come to closer to each other so that the front panel touches the partition walls. For this reason, the suction and exhaust is slightly performed (for instance, approximately 0.08MPa).

When pressure is evenly applied to the front and 10 back panels 10 and 20 from the outside, the front panel 10 comes into contact with the top ends of the partition walls on the back panel 20 as shown in Fig. 3. When the temperature is lowered in this state, the temperature of the sealant becomes lower than the softening temperature and the sealant hardens to seal the envelope 40. As a 15 result, the front panel 10 and the entire top ends of the partition walls are kept in absolute contact in the sealed envelope 40.

Note that the temperature is increased not at one 20 stroke to the sealing temperature that is slightly higher than the softening temperature of the sealant in the sealing process. The temperature is kept at lower than the sealing temperature for a certain period of time, for instance, at around 350°C for 30 minutes, to burn out the 25 binder material. This is effective at preventing the phosphor from deteriorating.

After the sealing process, the processing advances to the vacuum pumping process, the sealing process, and the discharge gas filling process to produce the PDP as in the case of the first embodiment.

5

(The Sixth Practical Example)

A specific explanation of the sixth practical example of the PDP producing method in which each of the processes is performed according to the fourth preferred embodiment will be given below.

In the sixth practical example, the PDP is manufactured according to the same temperature and pressure profiles as in the fourth practical example. The getter 76 is inserted into the getter tube 74 when the sealing has been performed and the temperature has been lowered to the room temperature. As the getter, vanadium, titanium, and iron alloy particles that are activated at 280°C are used.

In the conventional vacuum pumping process, it takes around two hours to lower the pressure in the envelope to 1.3×10^{-11} to 1.3×10^{-10} . On the other hand, pressure can be lowered in around one hour in the vacuum pumping process of the sixth practical example.

For the PDP that has been produced according to the above-mentioned method, lifting rarely occurs in the outer regions. Also, the discharge properties are even

compared with the conventional method in which pressure is applied only with clips. The level of noise from the outer regions is reduced by approximately several to 10db. The voltage at the start of discharge decreases by 5 approximately 5 to 10V. Furthermore, the discharge current decreases by approximately several to 10% and the effectiveness improves by around 10%.

Meanwhile, a comparative evaluation of the luminescence intensity (intensity/"y" chromaticity coordinate value) is performed on the phosphors of the PDP that has been sealed after dry gas is circulated as has been described and the PDP that has been sealed while the atmosphere is included in the PDP according to the conventional method. The comparative evaluation is performed by breaking the panel and irradiate Xe excimer lamp (with 173nm of wavelength). The luminescence intensity is improved by around 10% for the blue phosphor. Although the luminescence intensity is improved for all kinds of non-reactive dry gas, 15 significantly improved for dry air.

Note that while the sealing process and the vacuum pumping process have been performed in the same apparatus in the first to fourth preferred embodiments, it is not the only case. The sealing process and the 25 vacuum pumping process can be performed in different apparatuses.

Also, heat is not always applied to the envelope as a whole in the sealing process. It is possible to selectively apply a heat source such as the laser beam to the part where the envelope is to be sealed so as to 5 selectively apply heat to seal the envelope. In this case, the phosphors are not directly heated. As a result, it is assumed that the phosphors are rarely deteriorated by heat in the sealing process even if dry gas is not introduced into the discharge space.

As has been described, the present invention is a method of producing a gas discharge panel that includes: an envelope forming step for forming an envelope by providing over a first plate a second plate so that the second plate faces a main surface of the first plate, on which partition walls for partitioning light emitting cells have been formed; a sealing step for sealing the envelope with a sealant along outer edges of the first and second plates; an exhaust step for exhausting gas from the envelope; and a filling step for filling the envelope with a discharge gas, wherein the exhaust step 10 includes: a substep for evacuating the envelope; a substep for filling the envelope with a cleaning gas that includes as a constituent a gas that substantially causes no impurity in the discharge gas; and a substep for re- 15 evacuating the envelope.

Also, the present invention is a method of

producing a gas discharge panel that includes: an envelope forming step for forming an envelope by providing over a first plate a second plate so that the second plate faces a main surface of the first plate, on which partition walls for partitioning light emitting cells have been formed; a sealing step for sealing the envelope with a sealant along outer edges of the first and second plates; an exhaust step for exhausting gas from the envelope; and a filling step for filling the envelope with a discharge gas, wherein the exhaust step includes: a substep for evacuating the envelope; and a substep for exhausting gas from the envelope while a cleaning gas is circulated through the envelope, the cleaning gas including as a constituent a gas that substantially causes no impurity in the discharge gas.

Unlike the conventional method, gas is not only exhausted from the envelope as in the case of the conventional producing method. According to these producing methods, gas is exhausted from the envelope after the envelope is filled with the cleaning gas or while the cleaning gas is circulated through the envelope. As a result, the concentration of impurity gas in the envelope can be swiftly (in a short period of time) lowered compared with the conventional method. The higher definition the gas discharge panel, the more significant the effective. This is because it takes

longer to lower the impurity gas concentration as the definition is increased in general.

Note that when gas is exhaust from the envelope after the envelope is filled with the cleaning gas, it is 5 more preferable to exhaust gas after a certain period of time has elapsed since the envelope is filled with the cleaning gas.

Here, the sealant can be disposed between the first and second plates, the entire envelope can be 10 heated at a temperature that is no lower than one of a softening point and a melting point of the sealant while a pressure in the envelope can be set lower than a pressure outside of the envelope, and the envelope can be cooled at the sealing step. Note that lead alloy can be 15 used as the sealant.

As a result, the envelope is sealed so that the entire top ends of the partition walls almost come in contact with the plate that faces the partition walls.

Here, a step for inserting a getter into a 20 container that is linked to an internal space of the envelope can be included between the sealing step and the exhaust step.

As a result, the impurity gas can be removed from the envelope more swiftly.

25 Here, the entire envelope can be heated at a temperature that is no higher than one of a softening

point and a melting point of the sealant at the exhaust step. Note that when the getter is used as in the case described above, it is preferable that the activation temperature of the getter is within the range of the 5 heating temperature.

As a result, the impurity can be removed from the envelope more swiftly.

Here, the entire envelope can be cooled to a temperature that is higher than room temperature and no 10 higher than one of the softening point and the melting point of the sealant at the sealing step.

By doing so, a process in which the temperature is lowered to the room temperature once and then increased to the exhaust baking temperature is not 15 included the processing. As a result, the processing can advance to the next step, the exhaust step earlier.

Here, the sealing step can include: a substep for disposing the sealant between the first and second plates, and heating the entire envelope to a temperature 20 that is no lower than one of a softening point and a melting point of the sealant while a dry gas is circulated through the envelope; and a substep for heating the entire envelope at a temperature that is no lower than one of the softening point and the melting 25 point of the sealant while a pressure in the envelope is set to be lower than a pressure outside of the envelope,

and cooling the envelope.

By doing so, the sealing step is performed while the envelope is filled with the dry gas. As a result, the heat deterioration of the phosphors can be prevented.

5 Here, the sealant can be disposed between the first and second plates, sealed edges of the first and second plates can be heated at a temperature that is no lower than one of a softening point and a melting point of the sealant while a pressure in the envelope is set lower than a pressure outside of the envelope, and the envelope can be cooled at the sealing step.

10 Here, it is most preferable to use the discharge gas as the cleaning gas.

15 This is because there is no possibility that the cleaning gas is an impurity gas for the discharge gas with which the envelope is filled at the filling step, which comes after the exhaust step.

20 Here, a noble gas can be used as the discharge gas.

25 Here, the noble gas can include at least one of helium, neon, argon, and xenon.

Here, the light emitting cells can be formed by positioning a first group of parallel electrodes on the first plate orthogonally to a second group of parallel electrodes on the second plate with a distance between the first and second electrode groups.

Although the present invention has been fully described by way of examples with reference to the accompanying drawings, it is to be noted that various changes and modifications will be apparent to those skilled in the art. Therefore, unless such changes and modifications depart from the scope of the present invention, they should be construed as being included therein.

10 INDUSTRIAL USE POSSIBILITY

The method of producing gas discharge panel according to the present invention can be applied to manufacturing the PDP and the like that is used as the display such as the monitor of the TV set, the computer, and the like.

CLAIMS

1 1. A method of producing a gas discharge panel,
2 comprising:

3 an envelope forming step for forming an envelope
4 by providing over a first plate a second plate so that
5 the second plate faces a main surface of the first plate,
6 on which partition walls for partitioning light emitting
7 cells have been formed;

8 a sealing step for sealing the envelope with a
9 sealant along outer edges of the first and second plates;

10 an exhaust step for exhausting gas from the
11 envelope; and

12 a filling step for filling the envelope with a
13 discharge gas, wherein

14 the exhaust step includes:

15 a substep for evacuating the envelope;

16 a substep for filling the envelope with a
17 cleaning gas that includes as a constituent a gas that
18 substantially causes no impurity in the discharge gas;
19 and

20 a substep for re-evacuating the envelope.

1 2. A method of producing a gas discharge panel,
2 comprising:

3 an envelope forming step for forming an envelope

4 by providing over a first plate a second plate so that
5 the second plate faces a main surface of the first plate,
6 on which partition walls for partitioning light emitting
7 cells have been formed;

8 a sealing step for sealing the envelope with a
9 sealant along outer edges of the first and second plates;

10 an exhaust step for exhausting gas from the
11 envelope; and

12 a filling step for filling the envelope with a
13 discharge gas, wherein

14 the exhaust step includes:

15 a substep for evacuating the envelope; and

16 a substep for exhausting gas from the envelope
17 while a cleaning gas is circulated through the envelope,
18 the cleaning gas including as a constituent a gas that
19 substantially causes no impurity in the discharge gas.

1 3. The gas discharge panel producing method
2 according to Claim 1, wherein the sealant is disposed
3 between the first and second plates, the entire envelope
4 is heated at a temperature that is no lower than one of a
5 softening point and a melting point of the sealant while
6 a pressure in the envelope is set lower than a pressure
7 outside of the envelope, and the envelope is cooled at
8 the sealing step.

1 4. The gas discharge panel producing method
2 according to Claim 2, wherein the sealant is disposed
3 between the first and second plates, the entire envelope
4 is heated at a temperature that is no lower than one of a
5 softening point and a melting point of the sealant while
6 a pressure in the envelope is set lower than a pressure
7 outside of the envelope, and the envelope is cooled at
8 the sealing step.

1 5. The gas discharge panel producing method
2 according to Claim 1, wherein a step for inserting a
3 getter into a container that is linked to an internal
4 space of the envelope is included between the sealing
5 step and the exhaust step.

1 6. The gas discharge panel producing method
2 according to Claim 2, wherein a step for inserting a
3 getter into a container that is linked to an internal
4 space of the envelope is included between the sealing
5 step and the exhaust step.

1 7. The gas discharge panel producing method
2 according to Claim 3, wherein a step for inserting a
3 getter into a container that is linked to an internal
4 space of the envelope is included between the sealing
5 step and the exhaust step.

1 8. The gas discharge panel producing method
2 according to Claim 4, wherein a step for inserting a
3 getter into a container that is linked to an internal
4 space of the envelope is included between the sealing
5 step and the exhaust step.

1 9. The gas discharge panel producing method
2 according to Claim 1, wherein the entire envelope is
3 heated at a temperature that is no higher than one of a
4 softening point and a melting point of the sealant at the
5 exhaust step.

1 10. The gas discharge panel producing method
2 according to Claim 2, wherein the entire envelope is
3 heated at a temperature that is no higher than one of a
4 softening point and a melting point of the sealant at the
5 exhaust step.

1 11. The gas discharge panel producing method
2 according to Claim 3, wherein the entire envelope is
3 heated at a temperature that is no higher than one of the
4 softening point and the melting point of the sealant at
5 the exhaust step.

1 12. The gas discharge panel producing method

2 according to Claim 4, wherein the entire envelope is
3 heated at a temperature that is no higher than one of the
4 softening point and the melting point of the sealant at
5 the exhaust step.

1 13. The gas discharge panel producing method
2 according to Claim 5, wherein the entire envelope is
3 heated at a temperature that is no higher than one of a
4 softening point and a melting point of the sealant at the
5 exhaust step.

1 14. The gas discharge panel producing method
2 according to Claim 6, wherein the entire envelope is
3 heated at a temperature that is no higher than one of a
4 softening point and a melting point of the sealant at the
5 exhaust step.

1 15. The gas discharge panel producing method
2 according to Claim 7, wherein the entire envelope is
3 heated at a temperature that is no higher than one of the
4 softening point and the melting point of the sealant at
5 the exhaust step.

1 16. The gas discharge panel producing method
2 according to Claim 8, wherein the entire envelope is
3 heated at a temperature that is no higher than one of the

4 softening point and the melting point of the sealant at
5 the exhaust step.

1 17. The gas discharge panel producing method
2 according to Claim 3, wherein the entire envelope is
3 cooled to a temperature that is higher than room
4 temperature and no higher than one of the softening point
5 and the melting point of the sealant at the sealing step.

1 18. The gas discharge panel producing method
2 according to Claim 4, wherein the entire envelope is
3 cooled to a temperature that is higher than room
4 temperature and no higher than one of the softening point
5 and the melting point of the sealant at the sealing step.

1 19. The gas discharge panel producing method
2 according to Claim 11, wherein the entire envelope is
3 cooled to a temperature that is higher than room
4 temperature and no higher than one of the softening point
5 and the melting point of the sealant at the sealing step.

1 20. The gas discharge panel producing method
2 according to Claim 12, wherein the entire envelope is
3 cooled to a temperature that is higher than room
4 temperature and no higher than one of the softening point
5 and the melting point of the sealant at the sealing step.

1 21. The gas discharge panel producing method
2 according to Claim 1, wherein the sealing step includes:

3 a substep for disposing the sealant between the
4 first and second plates, and heating the entire envelope
5 to a temperature that is no lower than one of a softening
6 point and a melting point of the sealant while a dry gas
7 is circulated through the envelope; and

8 a substep for heating the entire envelope at a
9 temperature that is no lower than one of the softening
10 point and the melting point of the sealant while a
11 pressure in the envelope is set to be lower than a
12 pressure outside of the envelope, and cooling the
13 envelope.

1 22. The gas discharge panel producing method
2 according to Claim 2, wherein the sealing step includes:

3 a substep for disposing the sealant between the
4 first and second plates, and heating the entire envelope
5 to a temperature that is no lower than one of a softening
6 point and a melting point of the sealant while a dry gas
7 is circulated through the envelope; and

8 a substep for heating the entire envelope at a
9 temperature that is no lower than one of the softening
10 point and the melting point of the sealant while a
11 pressure in the envelope is set to be lower than a

12 pressure outside of the envelope, and cooling the
13 envelope.

1 23. The gas discharge panel producing method
2 according to Claim 21, wherein a step for inserting a
3 getter into a container that is linked to an internal
4 space of the envelope is included between the sealing
5 step and the exhaust step.

1 24. The gas discharge panel producing method
2 according to Claim 22, wherein a step for inserting a
3 getter into a container that is linked to an internal
4 space of the envelope is included between the sealing
5 step and the exhaust step.

1 25. The gas discharge panel producing method
2 according to Claim 21, wherein the entire envelope is
3 heated at a temperature that is no higher than one of the
4 softening point and the melting point of the sealant at
5 the exhaust step.

1 26. The gas discharge panel producing method
2 according to Claim 22, wherein the entire envelope is
3 heated at a temperature that is no higher than one of the
4 softening point and the melting point of the sealant at
5 the exhaust step.

1 27. The gas discharge panel producing method
2 according to Claim 23, wherein the entire envelope is
3 heated at a temperature that is no higher than one of the
4 softening point and the melting point of the sealant at
5 the exhaust step.

1 28. The gas discharge panel producing method
2 according to Claim 24, wherein the entire envelope is
3 heated at a temperature that is no higher than one of the
4 softening point and the melting point of the sealant at
5 the exhaust step.

1 29. The gas discharge panel producing method
2 according to Claim 21, wherein the entire envelope is
3 cooled to a temperature that is higher than a room
4 temperature and no higher than one of the softening point
5 and the melting point of the sealant at the sealing step.

1 30. The gas discharge panel producing method
2 according to Claim 22, wherein the entire envelope is
3 cooled to a temperature that is higher than a room
4 temperature and no higher than one of the softening point
5 and the melting point of the sealant at the sealing step.

1 31. The gas discharge panel producing method

2 according to Claim 25, wherein the entire envelope is
3 cooled to a temperature that is higher than a room
4 temperature and no higher than one of the softening point
5 and the melting point of the sealant at the sealing step.

1 32. The gas discharge panel producing method
2 according to Claim 26, wherein the entire envelope is
3 cooled to a temperature that is higher than a room
4 temperature and no higher than one of the softening point
5 and the melting point of the sealant at the sealing step.

1 33. The gas discharge panel producing method
2 according to Claim 1, wherein the sealant is disposed
3 between the first and second plates, sealed edges of the
4 first and second plates are heated at a temperature that
5 is no lower than one of a softening point and a melting
6 point of the sealant while a pressure in the envelope is
7 set lower than a pressure outside of the envelope, and
8 the envelope is cooled at the sealing step.

1 34. The gas discharge panel producing method
2 according to Claim 2, wherein the sealant is disposed
3 between the first and second plates, sealed edges of the
4 first and second plates are heated at a temperature that
5 is no lower than one of a softening point and a melting
6 point of the sealant while a pressure in the envelope is

7 set lower than a pressure outside of the envelope, and
8 the envelope is cooled at the sealing step.

1 35. The gas discharge panel producing method
2 according to Claim 33, wherein a step for inserting a
3 getter into a container that is linked to an internal
4 space of the envelope is included between the sealing
5 step and the exhaust step.

1 36. The gas discharge panel producing method
2 according to Claim 34, wherein a step for inserting a
3 getter into a container that is linked to an internal
4 space of the envelope is included between the sealing
5 step and the exhaust step.

1 37. The gas discharge panel producing method
2 according to Claim 33, wherein the entire envelope is
3 heated at a temperature that is no higher than one of the
4 softening point and the melting point of the sealant at
5 the exhaust step.

1 38. The gas discharge panel producing method
2 according to Claim 34, wherein the entire envelope is
3 heated at a temperature that is no higher than one of the
4 softening point and the melting point of the sealant at
5 the exhaust step.

1 39. The gas discharge panel producing method
2 according to Claim 35, wherein the entire envelope is
3 heated at a temperature that is no higher than one of the
4 softening point and the melting point of the sealant at
5 the exhaust step.

1 40. The gas discharge panel producing method
2 according to Claim 36, wherein the entire envelope is
3 heated at a temperature that is no higher than one of the
4 softening point and the melting point of the sealant at
5 the exhaust step.

1 41. The gas discharge panel producing method
2 according to one of Claims 1 to 40, wherein the cleaning
3 gas is the discharge gas.

1 42. The gas discharge panel producing method
2 according to Claim 41, wherein the discharge gas is a
3 noble gas.

1 43. The gas discharge panel producing method
2 according to Claim 42, wherein the noble gas includes at
3 least one of helium, neon, argon, and xenon.

1 44. The gas discharge panel producing method

2 according to one of Claims 1 to 40, wherein the light
3 emitting cells are formed by positioning a first group of
4 parallel electrodes on the first plate orthogonally to a
5 second group of parallel electrodes on the second plate
6 with a distance between the first and second electrode
7 groups.

1 45. The gas discharge panel producing method
2 according to Claim 41, wherein the light emitting cells
3 are formed by positioning a first group of parallel
4 electrodes on the first plate orthogonally to a second
5 group of parallel electrodes on the second plate with a
6 distance between the first and second electrode groups.

1 46. The gas discharge panel producing method
2 according to Claim 42, wherein the light emitting cells
3 are formed by intersecting a first group of electrodes
4 that have been disposed on the first plate in parallel
5 and a second group of electrodes that have been disposed
6 on the second plate in parallel with a distance between
7 the first and second groups.

1 47. The gas discharge panel producing method
2 according to Claim 43, wherein the light emitting cells
3 are formed by intersecting a first group of electrodes
4 that have been disposed on the first plate in parallel

5 and a second group of electrodes that have been disposed
6 on the second plate in parallel with a distance between
7 the first and second groups.

ABSTRACT

A method of producing a gas discharge panel capable of an efficient exhausting in the exhaust process. In a vacuum pumping process, with an open/close valve (53f) opened to a suitable degree while heating (baking) a heating furnace (51) to a temperature (exhaust baking temperature) lower than the softening temperature of a sealant layer, a turbo-molecular pump (53b) and a rotary pump (53c) are actuated to evacuate an envelope (40) until a vacuum is created, whereupon a discharge gas is introduced from a gas introducing system (52) into the envelope (40) until a predetermined pressure (for example, 0.05MPa) is produced therein. Thereafter, the discharge gas introduction from the gas introducing system (52) is stopped, and the discharge gas in the envelope is sucked out through a suction exhaust system (53), thereby re-establishing a vacuum state in the envelope (40).

09/744227

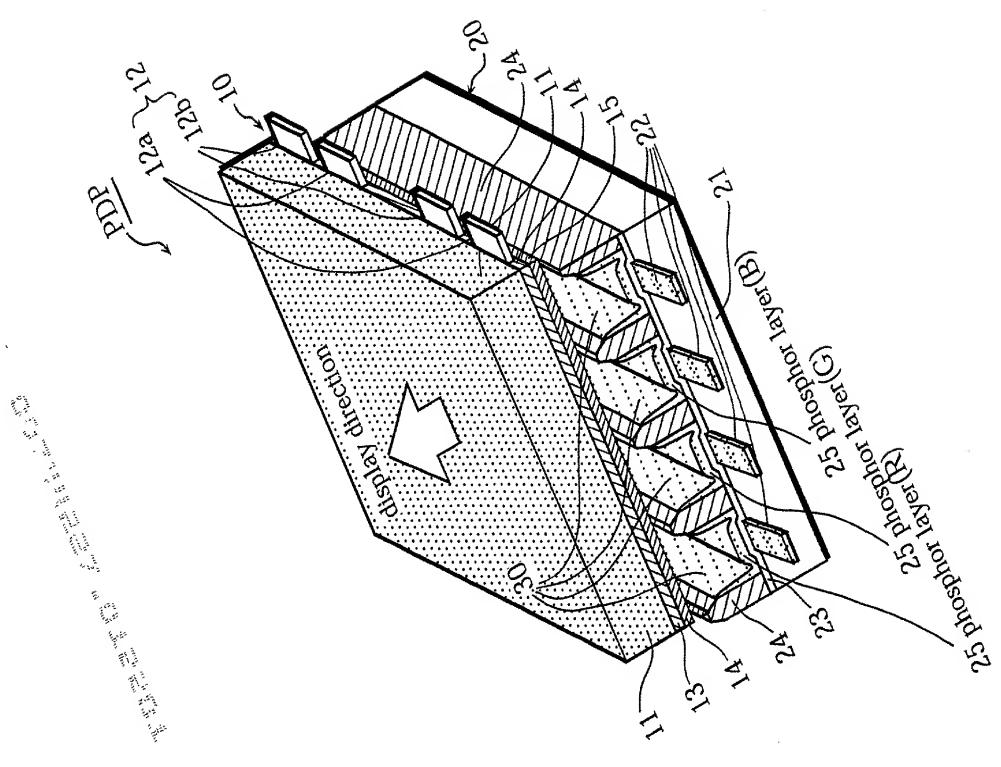


FIG. 1

FIG.2

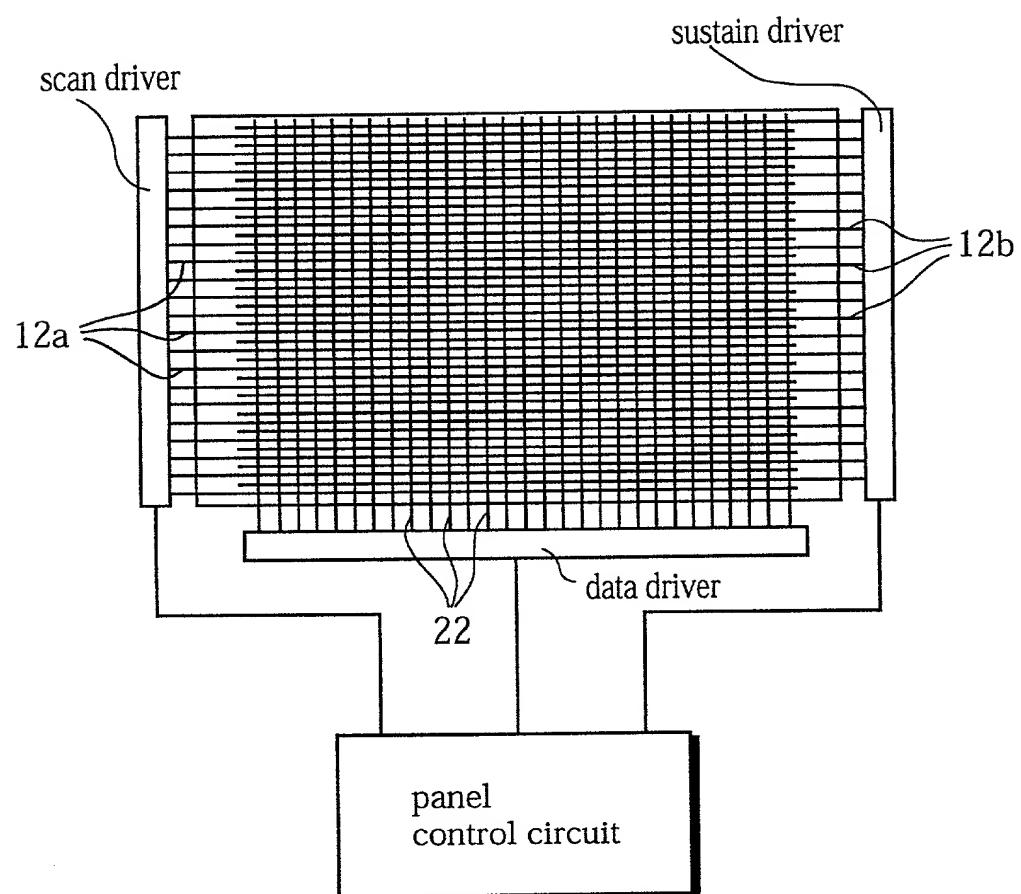
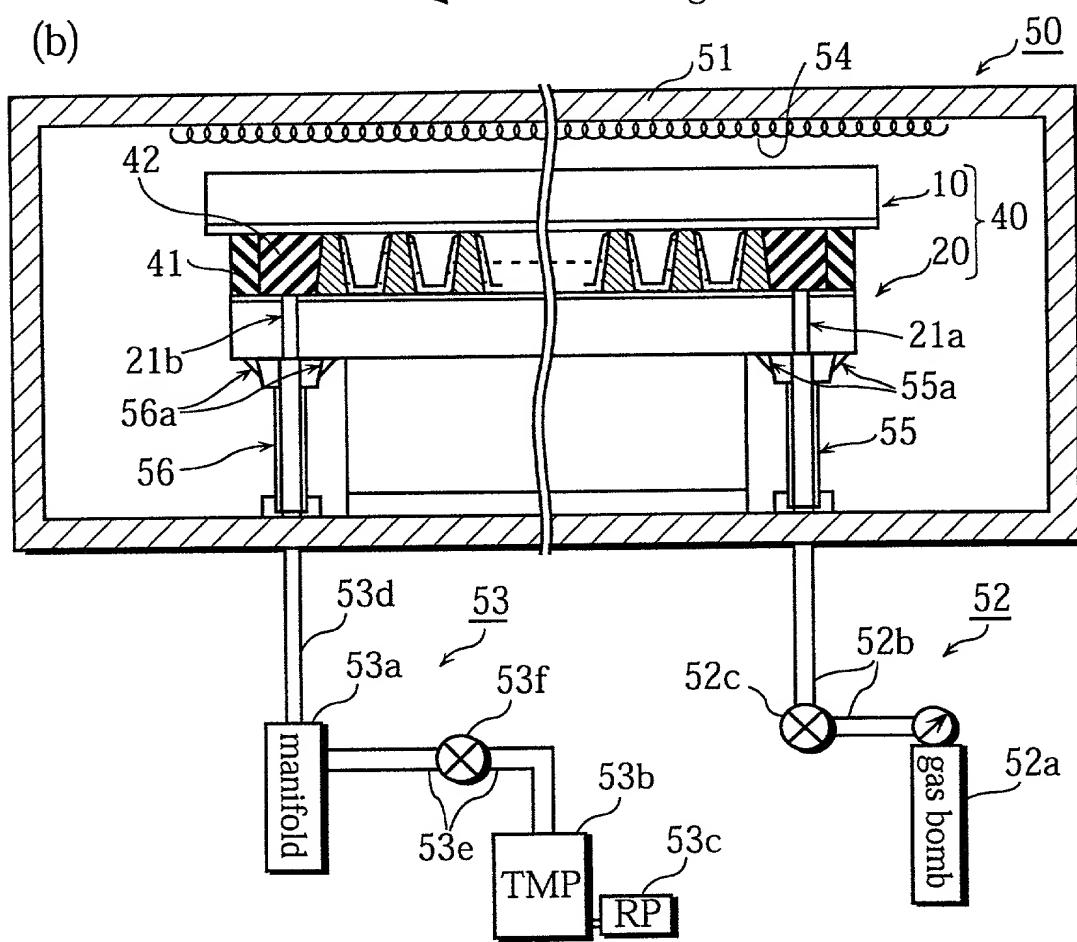
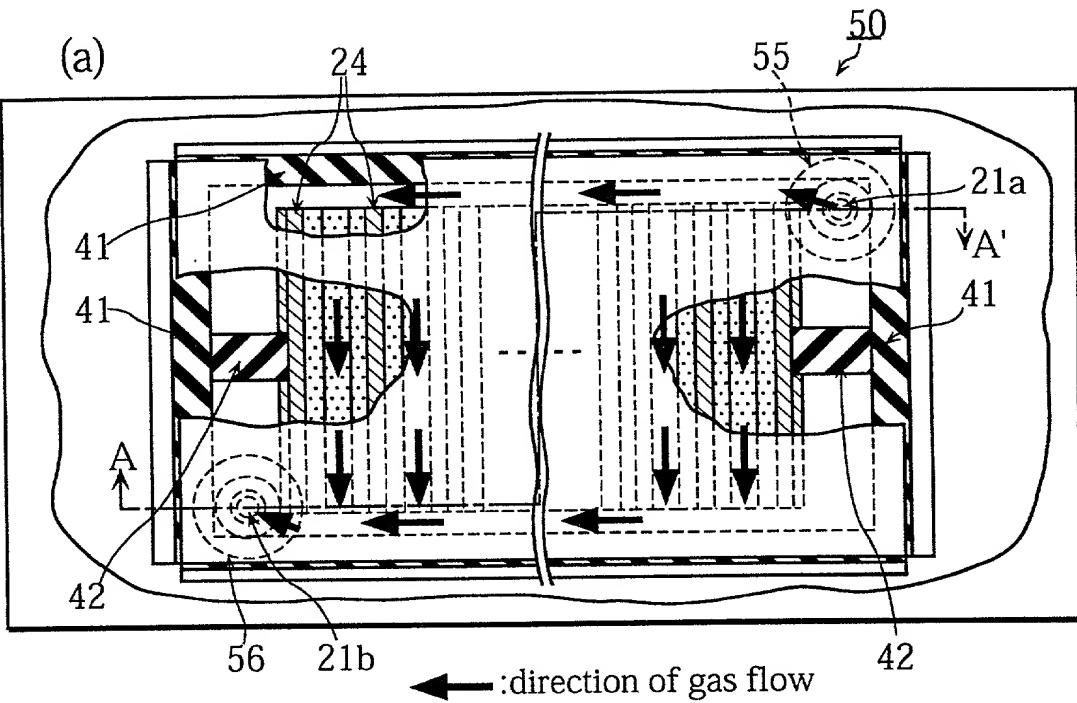
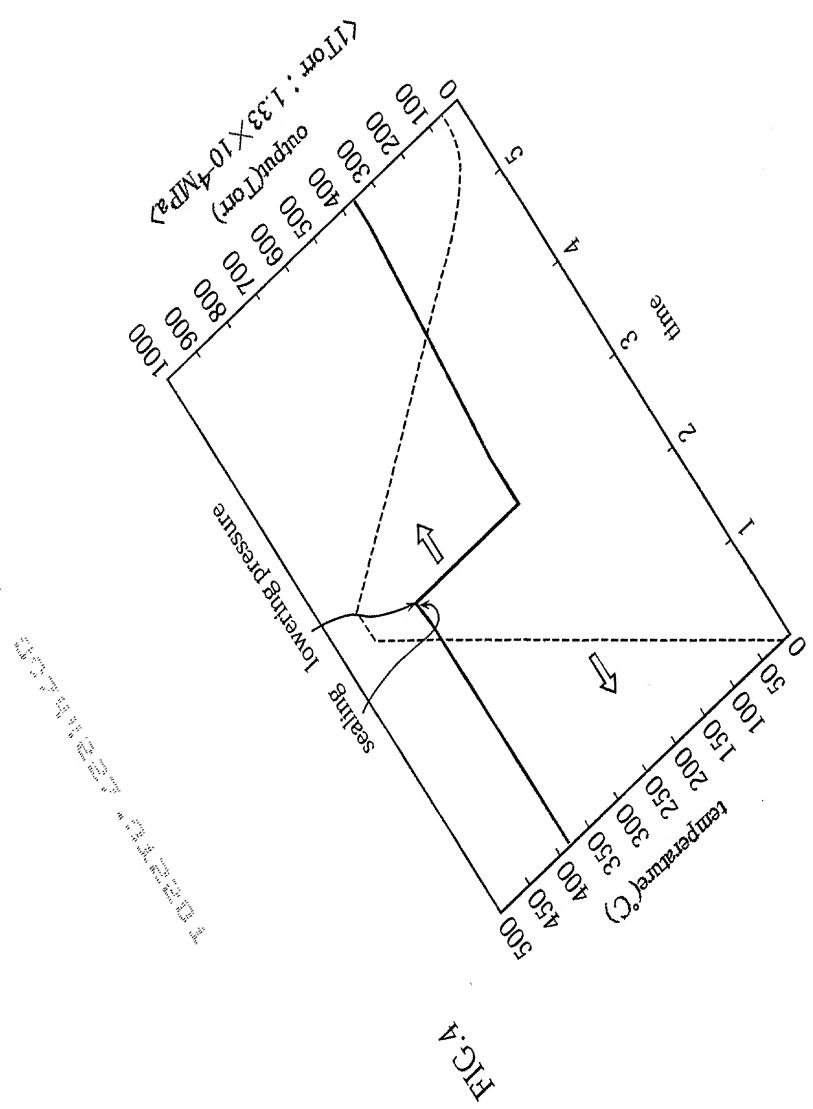


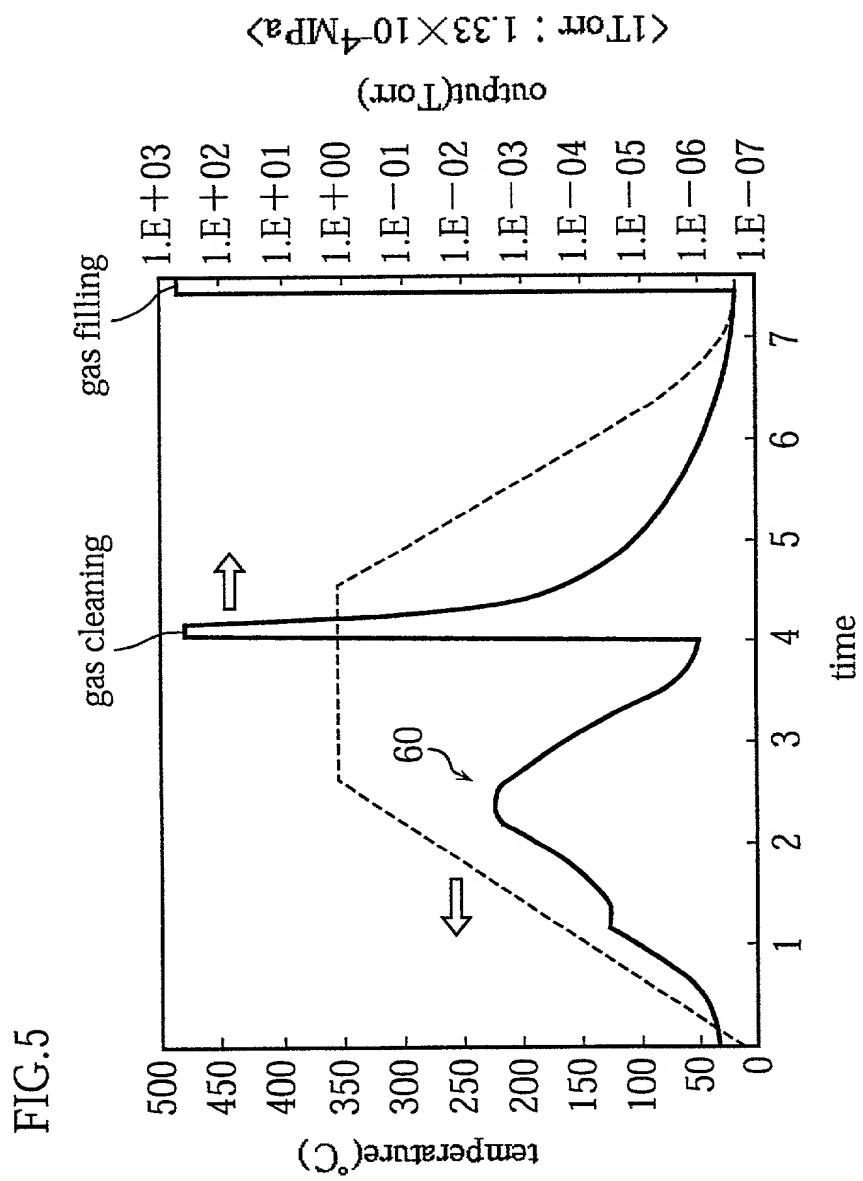
FIG.3



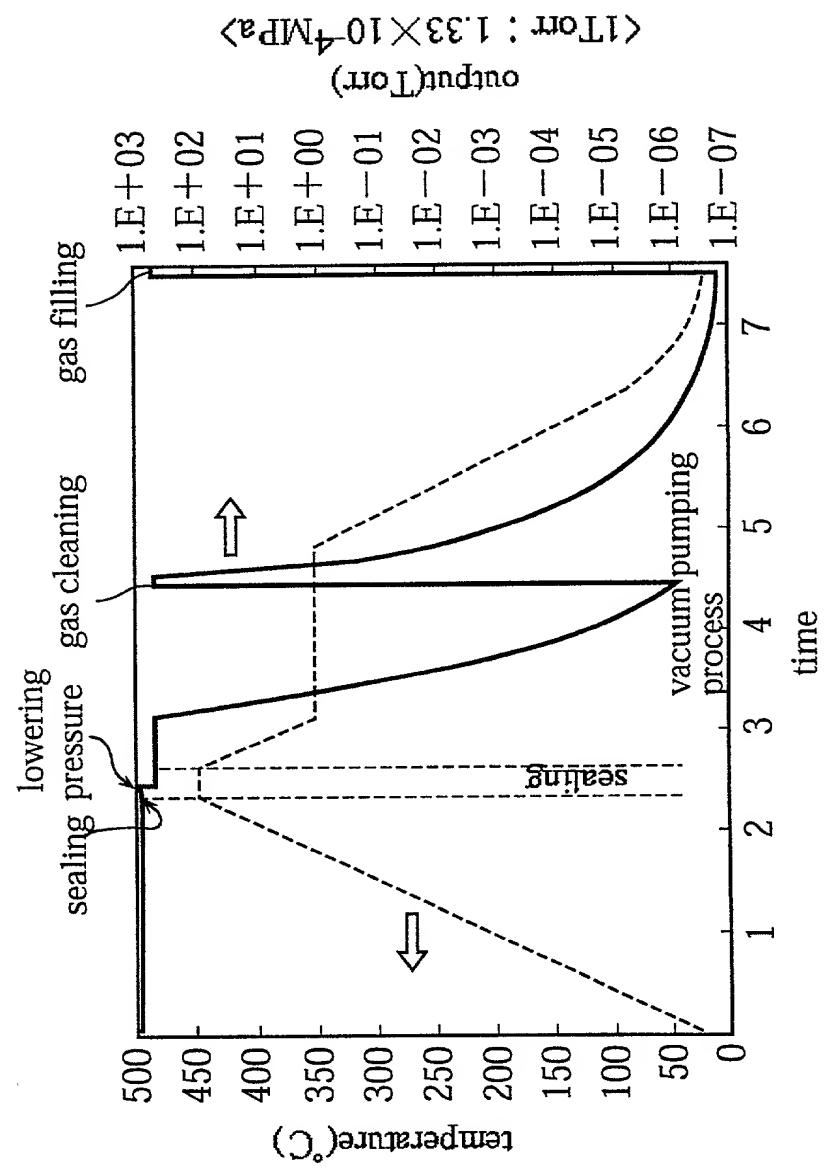
09/744227



09/744227



09/744227



09/744227

FIG.7

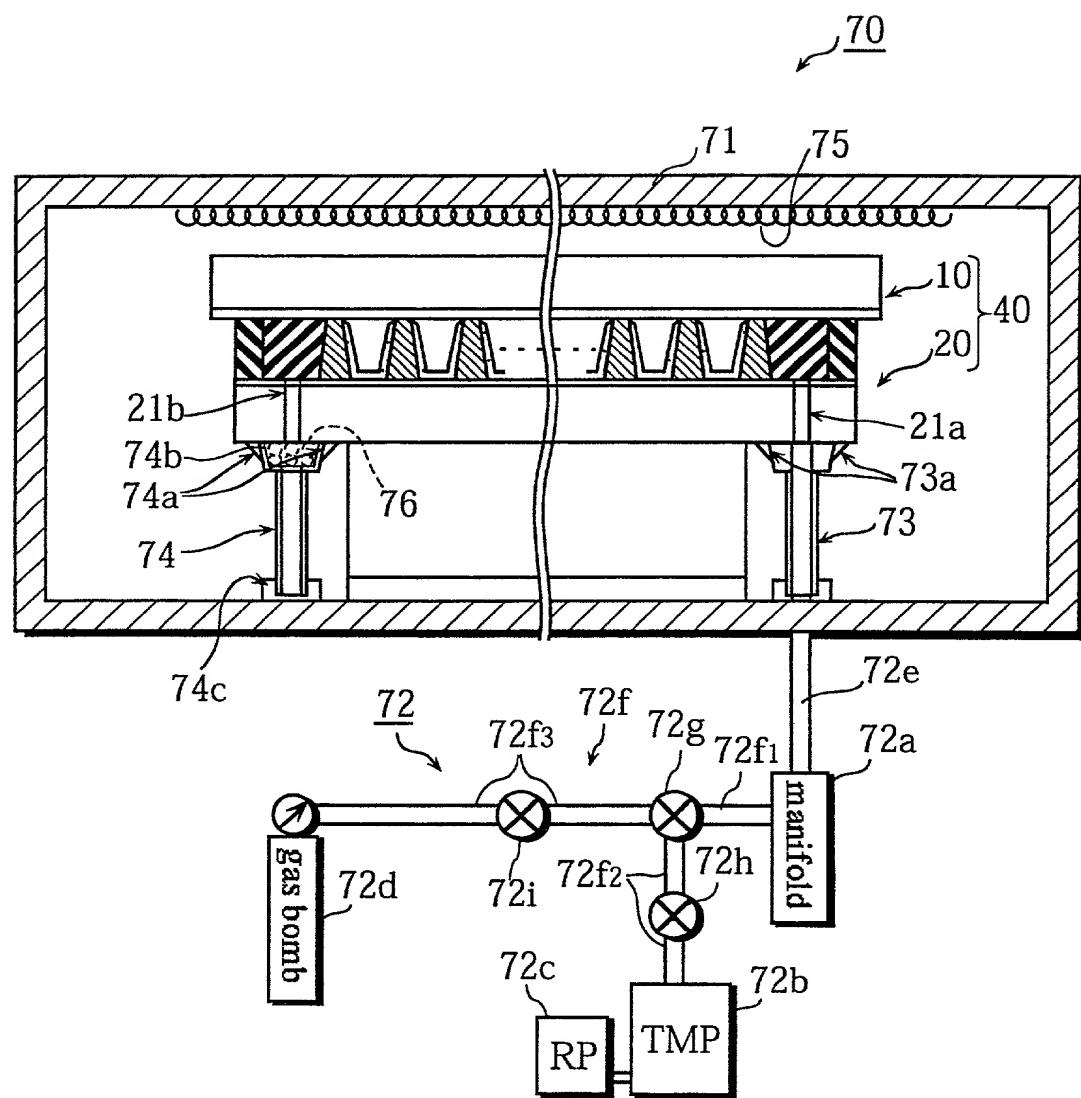
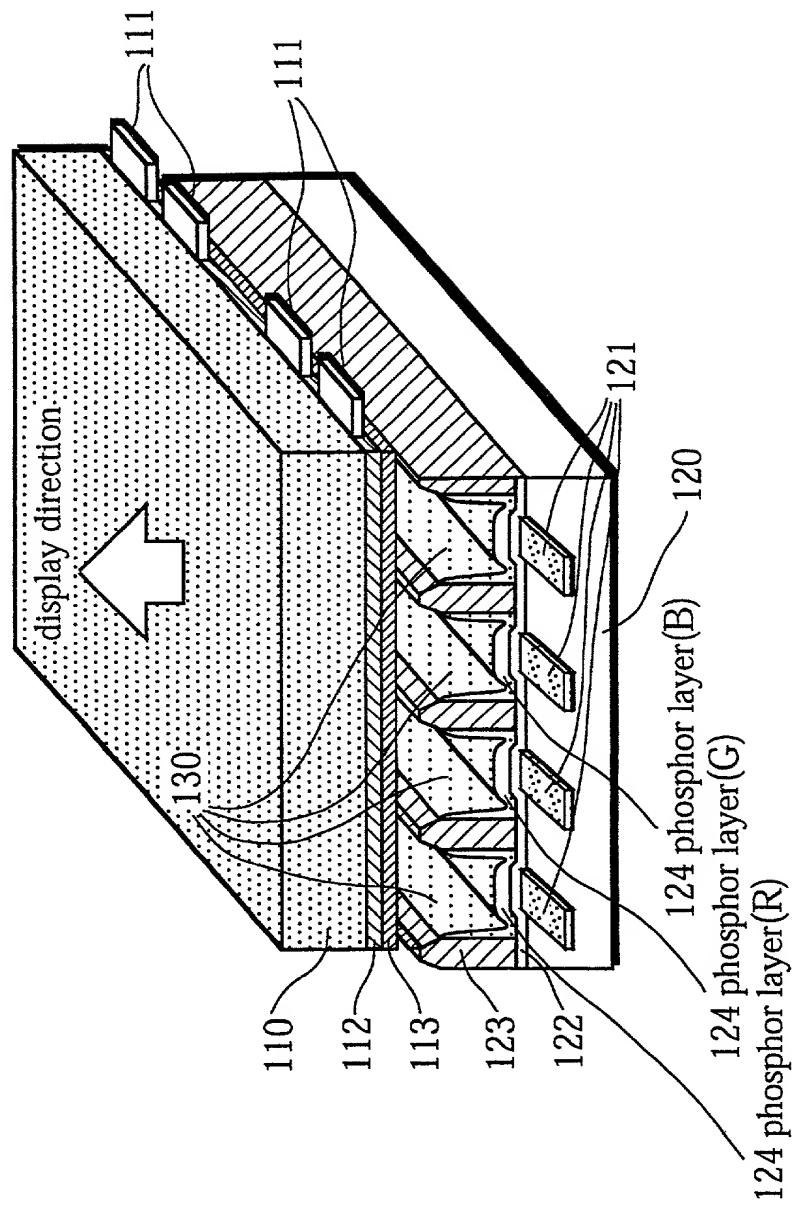


FIG. 8



Docket No.

Declaration and Power of Attorney For Patent Application

English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

METHOD OF PRODUCING GAS DISCHARGE PANEL

the specification of which

(check one)

is attached hereto.

was filed on May 17, 2000 as United States Application No. or PCT International Application Number PCT/JP00/03154
and was amended on _____

(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, Section 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119(a)-(d) or Section 365(b) of any foreign application(s) for patent or inventor's certificate, or Section 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate or PCT International application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)

Priority Not Claimed

11-139719 (Number)	Japan (Country)	20/May/1999 (Day/Month/Year Filed)	<input type="checkbox"/>
11-147937 (Number)	Japan (Country)	27/May/1999 (Day/Month/Year Filed)	<input type="checkbox"/>
 (Number)	 (Country)	 (Day/Month/Year Filed)	<input type="checkbox"/>

I hereby claim the benefit under 35 U.S.C. Section 119(e) of any United States provisional application(s) listed below:

(Application Serial No.)	(Filing Date)
(Application Serial No.)	(Filing Date)
(Application Serial No.)	(Filing Date)

I hereby claim the benefit under 35 U. S. C. Section 120 of any United States application(s), or Section 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. Section 112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, C. F. R., Section 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application:

(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)
(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)
(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. (list name and registration number)

Joseph W. Price, Reg. No. 25,124

Doyle B. Johnson, Reg. No. 39,240

Albin H. Gess, Reg. No. 25,726

Michael J. Moffatt, Reg. No. 39,304

Franklin D. Ubell, Reg. No. 27,009

Bradley D. Blanche, Reg. No. 38,387

Send Correspondence to: Joseph W. Price
PRICE, GESS & UBELL
2100 S.E. Main St., Ste. 250
Irvine, CA 92614

Direct Telephone Calls to: (name and telephone number)
Joseph W. Price, 949/261-8433

Full name of sole or first inventor	<u>Hidetaka HTGASHINO</u>	
Sole or first inventor's signature	<u>Hidetaka Higashino</u> Date <u>January 15, 2001</u>	
Residence	31-9, Hikaridai 7-chome, Seikacho, Souraku-gun, <u>Kyoto</u> 619-0237 Japan <u>JPX</u>	
Citizenship	Japan	
Post Office Address	same as residence	

Full name of second inventor, if any	<u>Nobuaki NAGAO</u>	
Second inventor's signature	<u>Nobuaki Nagao</u> Date <u>January 15, 2001</u>	
Residence	3-205, Myoukenzaka 3-chome, Katano-shi, <u>Osaka</u> 576-0021 Japan <u>JPX</u>	
Citizenship	Japan	
Post Office Address	same as residence	

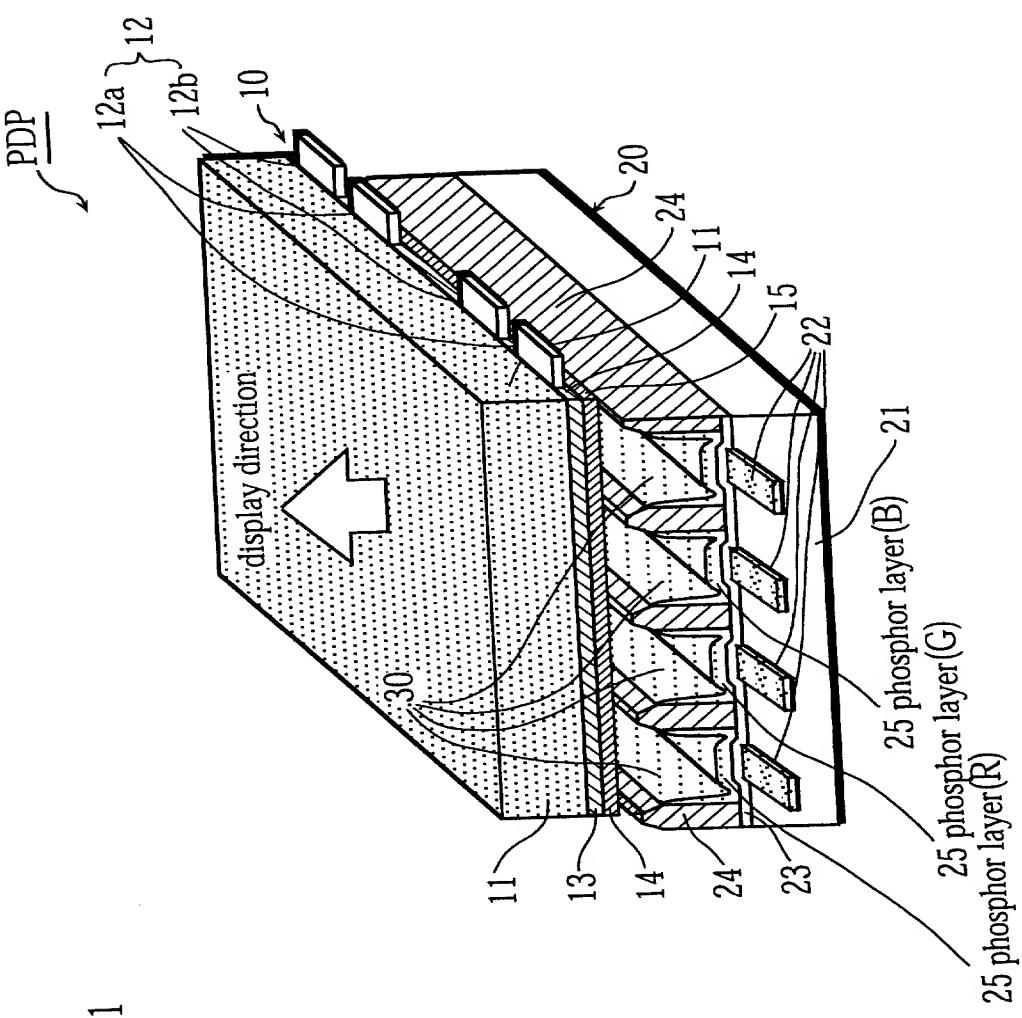
UNITED STATES PATENT AND TRADEMARK OFFICE
DOCUMENT CLASSIFICATION BARCODE SHEET



CATEGORY:

CLEARED

ADDRESS
CONTACT IF FOUND:



09/744227

